

exclusively for designers and design managers in electronics



Dynamic Laser Trimming

The engineers who designed this electronic tube anode could have given the production men a hard time. It was to be die-drawn from a single piece of copper in three reverse draw planes to a total draw-depth of 12 inches. But conventional, easily drawn copper alloys were out. Conductivity requirements, both electrical and thermal, ruled out most of them. The water cooled anode had to maintain maximum electrical efficiency while dissipating 22.5 kW. Outgassing specifications were even more critical: the anode would operate in a high vacuum and no impurities could be tolerated.

By specifying OFHC copper both the design and manufacturing problems were solved.

Uniform purity was the primary reason. OFHC copper is 99.99+% pure. That meant that production men could accurately predict the performance of the copper and design a drawing process to suit. And, purity eliminated outgassing. In addition AMAX certified conductivity of OFHC at 101% IACS. Good physical strength and good glass-to-metal seal-ability completed the picture.

OFHC copper may be the solution to your electrical and mechanical problems, too. We have all the data. Draw on it any time.

Specifying ductile copper without sacrificing conductivity and outgassing requirements is easy as OFHC.

It's a story you can draw on. Send for it.





Make Waves...



HP's 3310A is the function generator that gives you seven different waveforms-in three different modes-in one inexpensive package.

In its basic form, the 3310A gives you a continuous output of square waves, sine waves, and triangle waves - plus positive and negative ramps and pulses-for only \$595.

And for only \$140 more, you can get the 3310B, which lets you generate each of these seven waveforms in two other modes – single-cycle and multiple cycle "bursts." These can be triggered either manually or just about any waveform you can imagine

MW WW DU

by an external oscillator; startingpoint phase can be varied by \pm 90°.

In either the "A" or "B" version, the 3310 gives you a choice of ten frequency ranges—from 0.0005 Hz to 5 MHz—and an output voltage range from 15 mV pk-pk to 15 V pk-pk into 50Ω load. Dc offset of ± 5 V into 50Ω load is also standard.

Both the 3310A and 3310B can be used in frequency-response and transient-response testing, as a waveform converter, for generating phase-coherent waveforms, and as a frequency multiplier or divider, among other things. Applications include testing television and communications systems, radar systems, and analog or digital circuits.

For further information on the 3310A and 3310B, contact your local HP field engineer, or write to Hewlett-Packard, Palo Alto, California 94304. In Europe: 1217 Meyrin-Geneva, Switzerland.



CIRCLE NO. 2

This Combination

Integrated circuit





CORDIP[™] Component Network

replaces this combination.



Integrated circuit plus 23 discrete resistors, capacitors, and diodes

Corning's new CORDIP[™] component networks take in much of what IC's leave out outboard discretes.

Unlike screened thick/thin film networks, CORDIP component networks give you custom combinations of discrete resistors, capacitors, and diodes in a dual in-line package.

With combinations of up to 20 components in a standard 14-pin package. Up to 23 in a 16-pin package.

With virtually unlimited circuit complexity. With all inter-connections inside the pretested package.

Which gives you greater reliability and fewer production losses.

Combinations of resistors, capacitors and diodes with different tolerances, temperature coefficients and ratings are available in one package.

Which makes it possible to give you almost any custom combination you specify.

Large orders or small.

And we can make prototypes quickly for you, with almost any combination you specify.

CORDIP component networks are ready to plug in and are fully compatible with IC sequencing and insertion equipment.

CORDIP component networks. You'll save a lot of board space and production costs; you'll gain a lot more reliability and flexibility.

Call or send us your circuit requirements. Corning Glass Works, Electronic Products Division, Corning, New York 14830. (607) 962-4444 Ext. 8684.

SPECIFICATIONS

	Resistors	<u>Capacitors</u>	Diodes
Range	10Ω-150K	10-10,000 pF	Low
Tolerance	from 1%	from 5%	Signal
TC	from 50 ppm	+ 2%, -10%	Planar
Ratio	>15,000:1	>1,000:1	Types

CORNING ELECTRONICS CIRCLE NO. 3



EXCLUSIVELY FOR DESIGNERS AND DESIGN MANAGERS IN ELECTRONICS

Cover

Cover photo from Motorola Semiconductor shows laser trimming of a hybrid IF detector. Both "L" and straight cuts are used, under computer direction. See news story on p. 10.

Design News

IC Applications Seminars Planned for Los Angeles . . . More Jobs Predicted for U.S. Engineers Because of 10% Surcharge . . . Connector Takes Rough Treatment.

Design Features

The second part of this MOS feature assesses which technologies will become standard and tells "who makes what."

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Designing Precision Integrators with High-Speed Mode Controls	34
Capacitance drift is a key factor that limits analog integrator performance. This design gets stability and curacy by ingenious use of a fixed capacitor.	ac-

Design Ideas

Switching Regulator Designed for Portable Equipment	39
Unlike some regulators, properly designed ones of the switching type offer high efficiency.	
Plagued by Triac Hysteresis?	42
A simple new IC solves snap-on, yet requires no additional parts.	

Circuit Design Award Entries

Proportional oven-temperature controller . . . Adjustable rectangular-wave oscillator interfaces with IC logic.

Progress in Products

LSI and LEDs Produce Truly Portable Digital Multimeter 49 Miniature Capacitor First with Multilayer Dielectric . . . Second-Source Log Amps with a Difference.

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Speakout-Bob Noyce of Intel Speaks out on the IC Industry, p. 28.



Everybody wants your components business.

But we're doing 6 things to earn it.

extra reliability into our components to let you build extra reliability into your systems. We offer documented reliability from ER through industrial, from precision through general purpose.

Pricing you'll like. For many product styles, our quantity resistor pricing is under 5¢ and often less than 3¢. And that's for tin oxide resistors that significantly outperform other metal films, wirewounds, carbon comps and metal glaze resistors.

Faster delivery. Our distributors can give you off-the-shelf delivery from an inventory of over 50,000,000

Extra reliability. We build components. And our "ball parks" lot of board space. are firm, real and reliable. This lets you keep expediting and inventory levels to a minimum.

Production savings. Our unique product configurations greatly simplify both hand insertion and automatic insertion operations. This saves you money. And our QC is so stringent, many of our customers have totally eliminated their incoming QC testing of our parts. This saves them money.

Product innovations. Like our new CORDIP™ Component Networks. With up to 23 discrete resistors/ capacitors/diodes in a miniature, pre-tested, plug-in package to save you time, money, and a whole ELECTRON

Sharper support. We've hand-picked the 30 most competent distributors in the country and built the industry's largest technically trained field force-then backed everything with a full team of specialists -to give you all the in-depth service you want and then some.

We too want your business. But we're doing 6 extra things to earn it.

Give us a chance to prove it. Write: Corning Glass Works, **Electronic Products Division**, Corning, New York 14830. Or call: (607) 962-4444, Extension 8381.



Resistors & Capacitors for guys who can't stand failures

with a little

İMAQİMATİON and the LIGHT EMITTING DIODE (packaged by Sloan) –a world of design possibilities lies ahead.

Sloan's long experience in the indicator light field has made it a natural to develop this package for the visible Light Emitting Diode (LED) — a packaged LED ready for installation in a host of indicator light applications.

Using the technology of the semiconductor, Sloan has designed this advanced LED — which already has long life and low power consumption — into an offthe-shelf ready to be used package.

- Red or White Lexan Lens.
- Forward Voltage: 5.0± .3 V for TTL Logic or other low voltages <u>as needed</u>.
- Resistor built in for voltage required.
- Dome or Flat Lens.
- Choice of Wire Wrap, solder or connector terminals.

Any low voltage Logic or D.C. conditions can be accommodated ... Or Sloan will design and build the lights to meet your special needs.

If indicator lights are your problem, Sloan is the answer.



CIRCLE NO. 5



Editorial

Design Decision Making In the 1970s

Once upon a time not so long ago, circuit design was considered very basic. People believed that if you gave the same design problem to two different groups of engineers, they would come up with very similar, although independently derived, solutions. Engineers were considered remoras¹ locked to basic circuit/system design procedures set forth by industry standard handbooks and texts.

Today that conservative view of the design engineer is gone. One of the nice things that has happened during the semiconductor era has been the emergence of the design engineer as a respected member of the electronics community.

It's a lot easier for circuit/system designers to move up into top-level positions today than it was 15 years ago. There are many reasons, of course, including easier access to business management courses,

¹ A remora is a fish with a suction disk by which it attaches itself to sharks, turtles and even ships, contenting itself to ride along wherever its source of transportation decides to go.

better understanding of rapidly moving technology, freedom to innovate and the availability of financial support to start out on their own.

But another major factor has been the changing responsibilities of the design engineer as economics became an increasing consideration in his everyday decision making.

The advent of thick- and thin-film technology helped immeasurably. Hybrid concepts gave the engineer, for the first time, a real choice of techniques to reach a particular goal. Integrated circuits have further expanded the realm of the designer to the point where he evaluates each move from the viewpoint of the present cost of implementation and the likely future cost at the time of production. If once a remora, the design engineer is today in every sense a businessman.

Jeny Eimlinder

Editorial Director

POWERTEC'S WINNING OEM MULTIPLES

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Model	(Output Pow	er	Unit
Number	±12V 0	$r \pm 15V$	5V	Price
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2L15D-2.8	3.0A	2.8A	NA	\$ 81.00
2R-70T	1.5A	1.3A	6.0A	\$ 86.00
2S-140T	3.0A	2.8A	12.0A	\$149.00

• REGULATION: Line $\pm .25\%$, Load $\pm .25\%$ • INPUT: 115 VAC \pm 10V 47-63Hz • RIPPLE: 1mv RMS 5 & 15V • RESPONSE: 50 μ sec typical • TEMPERATURE: 0°C to 40°C derated to 71°C • O.L. PROTECTION: Current limit/ foldback • Optional OVP available



CIRCLE NO. 6

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Editorial Office Addresses Executive (303) 388-4511 270 St. Paul St. Denver, Colo, 80206

New York (212) 689-3250 205 E. 42nd St. New York, N.Y. 10017

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When the lights go out, the only really portable Digital Multimeter goes on

...and on.

Run the Fluke 8100A 0.02% digital multimeter anywhere, anytime up to 8 full hours off the rechargeable battery pack. Printer output now available.

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There are twenty or thirty digital multimeters around that lay claim to portability. The only one you can move around easily and use without a nearby wall plug is ours. It's the only portable machine that works where you need a portable machine.

True portability is just part of the story. The Fluke 8100A, with an accuracy of 0.02% and a selling price of \$795, with rechargeable battery option, gives you nine times the accuracy of three digit instruments for half the price of comparable four digit multimeters. We've used a new A to D technique to give you an instrument with low power drain for eight-hour continuous battery operation without recharging. (line operation only \$695)

The Fluke 8100A measures ac and dc volts in four ranges to 1200 volts and ohms in five ranges to twelve megohms. Readout is four full digits plus "1" for 20% overranging. Features include an active 2-pole switchable filter and automatic polarity indicator. All functions are push-button selectable.

Also available are RF and high voltage probes, switched ac-dc current shunts, a ruggedized case, and data output (line operation only). John Fluke Mfg. Co., Inc., P.O. Box 7428, Seattle, Washington 98133. Phone (206) 774-2211. TWX: 910-449-2850/In Europe, address Fluke Nederland (N.V.), P.O. Box 5053, Tilburg, Holland. Phone: (04250) 70130. Telex: 884-50237/In the U.K., address Fluke International Corp., Garnett Close, Watford, WD2 4TT. Phone: Watford, 27769. Telex: 934583.

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CIRCLE NO. 7

Design News

Automatic Trimming Teams Laser and Computer

Laser trimming of film resistors continues to make inroads into areas once dominated by air abrasive (sandblasting) systems. The advantages offered by the laser technique — which include accuracy, speed of cut and cleanliness of the finished product have contributed to the continuing gains being made by these systems.

Motorola Semiconductor, a company that has spent long hours working with laser systems, is a good example to show how one company has brought the laser system to today's point of sophistication. At Motorola it all began with the use of a YAG laser to scribe zener diode wafers. Later, a CO, system was added to the hybrid circuit production area for thick-film resistor trimming. And most recently, dynamic trimming is being performed under computer control. In dynamic trimming, resistors are trimmed while the circuit is operational in order to obtain optimized circuit performance. **Fig. 1** shows this technique applied to a practical circuit. This is the automated equivalent of hand selecting one or two components for a critical position in a circuit to get the required performance from that circuit.

With a computer married to a laser trimming system, the statistics for accuracy and speed that accompany such a match are impressive. One in-



Demonstrating CAD of hybrid circuit. CAD system, consisting of light pen, CRT display and CDC 1700 computer, uses stored "polycell" designs to speed layouts. Computer displays numerical parameters associated with a selected design, such as resistor power dissipation, turn points for L-cut resistor trims, etc.

dicator of merit is a head traverse speed of 0.06 to 1.0 inches/sec that results in 1 to 2 resistor trims/sec.



Circuit is hybrid IF detector, part of an automatic paging system. Resistors range from 2 to 150 k Ω with tolerances from 1 to 8%. Trim is passive, and both L and straight-in cuts are used. Two monolithic custom chips later will be bonded onto the substrate. Total trim time is about 5 sec. All resistors are cermet thick film. Kerf is about 2 mils wide and 1.5 mils deep. Resistor sizes range from 30 by 30 mils to 140 by 20 mils. Laser is running at 2.5W, Q switching at 7.5 kHz.



Entire laser/computer resistor trimming system. Laser safety shield normally is in down position, to protect operator from laser light. In photo, protective cover is raised, with laser off. "Teletype", to right, inputs operator instructions to system. Manual control box can be used to operate laser, stage motors, etc., and also contains emergency shutdown button. Left rack cabinet contains controls, interconnection matrices, power supplies and a programmable bridge.



Research Mairichtion Nesson - Searchis Research Resear

(Depending on the number of resistors to be trimmed, a complete circuit normally takes about 10 sec for loading, trimming and unloading.) Another indication is that positioning (X-Y) accuracy is achieved to a resolution of ± 0.2 mils (± 5 -mil silkscreened resistor registration is acceptable for successful trimming). Resistor values after trim are accurate to within $\pm 0.1\%$. This is achieved by various cuts that include straightin, L and combinations of these. Such a laser trimming system is 10 times faster than its air-abrasive counterpart.

In the Motorola system (shown in the photos), the computer controls both the laser beam and the measurement. It controls the X-Y stage motors, commands the laser to begin or stop and programs the traverse speed of the head which is not constant during a trim.

An off-line, time-shared computer is also called upon for solving fielddistribution equations for a particular resistor. This time-shared computer is needed because of the extensive number of computations required. Field equations are solved to assess the effect of making L-cut turns at different points on the resistor.

In the future, Motorola engineers expect to add a rotary table for loading or unloading. This will speed the cycling of parts under the laser head. Laser head motion will probably be increased to 2 inches/sec, and perhaps even faster if mirrors are used. The limitation on speed stems from motor slew rate. As to tolerances, these probably will get down to $\pm 0.05\%$ without the need for major system redesign.



IC Applications Seminar Planned for Los Angeles

EDN/EEE and approximately 25 IC manufacturers will stage a pair of 2-day seminars in October at the International Hotel, Los Angeles, Calif. Linear ICs will be covered in the first seminar scheduled for Tuesday-

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Linear IC Program (First Day)

Wednesday, Oct. 5-6; Semiconductor Memories will be the topic at the second seminar, planned for Thursday-Friday, Oct. 7-8.

The papers being prepared for the program are applications-oriented

-aimed at helping IC users select recently announced ICs and correctly apply them to their particular needs. Application hints and considerations will be stressed.

The tentative program follows:

Linear IC Program (Second Day)

	ruesuay, Oct. 5, 19/1		
1	"Monolithic D/A and A/D Building Blocks"	L9	"Applying Digital/Analog Interface Circuits"
	Garth Wilson, Vice President, Engineering,		Don Jones, Applications Engineer.
	Precision Monolithics, Santa Clara, Calif.		Harris Semiconductor, Melbourne, Fla
2	"Advanced Bipolar and MOS Linear ICs and Their	L10	"Noise In Operational Amplifiers"
	Applications"	Ser Constant	Dave Fullagar, Engineering Manager for Analog Products
	Merle Hoover, Manager, Linear Integrated Circuits,		Intersil, Cupertino, Calif.
	Applications Engineering,	L11	"High-Speed Comparators"
	RCA, Somerville, N. J.		Jim Giles, Director of Engineering, Analog Operations
3	Topic To Be Announced		Advanced Micro Devices, Sunnyvale, Calif.
	Gus Pfaehler, Linear Applications,	L12	Topic To Be Announced
	Fairchild Semiconductor, Mountain View, Calif.		Colin Berry, Manager, Linear IC Development
ł	"IC Voltage Regulators"		Signetics, Santa Clara, Calif.
	Bob Mammano, Chief Engineer,	L13	"Common Problems and Solutions in Using Linear ICs"
	Silicon General, Westminster, Calif.		Karl Huehne, Industrial Applications Section Manager
5	"Designing with Ultralow-Drift Operational Amplifiers"		Motorola, Phoenix, Ariz.
	Doug Sullivan, President, Nova Devices, Affiliate of	L14	Topic To Be Announced
	Analog Devices, Norwood, Mass.		Joel Scheinberg, Linear Applications.
1	"Fast Settling Time Amplifiers"		National Semiconductor, Santa Clara, Calif.
	Dave Ludwig, Director of Engineering,	L15	"Applications for Micropower Amplifiers"
	Teledyne Philbrick, Dedham, Mass.		Wayne Folleta, Design Engineer.
	Topic and Speaker To Be Announced		Qualidyne, Sunnyvale, Calif.
	Teledyne Semiconductor, Palo Alto, Calif.	L16	"Designing with Micropower Operational Amplifiers"
3	"Designing with D/A and A/D Converters"	No. S.	Jim Bohorquez, Linear Products Manager.
	Jack Robertson, Executive Vice President,		Solitron Devices, San Diego, Calif.
	Zeltex, Concord, Calif.	L17	"Interface Circuits for Computer Systems"
			Dale Pippenger, Product Engineer.
			Texas Instruments Incorporated, Dallas, Texas
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	Semiconductor Memory Program (First Day)	9	Semiconductor Memory Program (Second Day)
	Semiconductor Memory Program (First Day) Thursday, Oct. 7, 1971	S F	emiconductor Memory Program (Second Day) riday, Oct. 8, 1971
1	Semiconductor Memory Program (First Day) Thursday, Oct. 7, 1971 "Field Programming vs Factory Programming of ROMs"	5 F M10	Semiconductor Memory Program (Second Day) riday, Oct. 8, 1971 "Memory System Design with MOS RAMs"
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CIRCLE NO. 8

More Jobs Predicted for U.S. Engineers Because of 10% Surcharge

The rate at which consumer and commercial equipment design jobs are going offshore should be slowed down by President Nixon's 10% surcharge on imports, according to scattered industry sources. For the most part, these were component makers who have been very conscious of design going abroad. When U.S. engineers aren't doing the full design, component makers have found it much less likely that U.S. components will be used.

"Now U.S. companies won't be so quick to go offshore once their products go into high volume," predicted John Yngve, president of Nortronics Co., Inc., Minneapolis, Minn.-a leading tape-head manufacturer. "All too often in the past we have had the painful experience of helping a U.S. manufacturer through the R&D phase of new product development and investing considerable engineering talent, in the hopes of getting his volume orders once the product goes into full production... only to see the product line go offshore and the Japanese and others cash in on the rewards."

"Right now we're worried that the very promising digital cassette products might suddenly go the way of the audio cassettes and be made almost wholly in Japan," Yngve said. "It is the old familiar pattern. There is a lot of new-product development going on in the U.S., but we hear of ominous developments in Europe and Japan. The President's message may have come in the nick of time."

Yngve agreed that U.S. engineers who thought they were in on the ground floor on a new product family have also been "betrayed" in such cases. When the product goes offshore, sooner or later the engineers' jobs go offshore with it.

The effect of the surcharge may be more psychological than absolute, according to Jack Stegenga, Weston, Newark, N. J. "It might take a surcharge as high as 50% to completely stop foreign competition in electronics," Stegenga stated. "Weston has been able to avoid head-on competition from the Japanese because the instruments we make typically sell in 10,000unit-per-year volume levels, not the million-unit-per-year levels that the Japanese like." Weston is well aware of the effect of Japanese competition, however, from experience with its photographic light meter lines.

"The surcharge will make U.S. manufacturers stop and think before they invest further in offshore sources," reasoned Ron Stannish, U.I.D., Hollywood, Fla. "I think the President made it clear that they will be hurting the U.S. if they do so, and our country can't stand too much more of this sort of harm."

Stannish, who is Marketing Manager for U.I.D., said that all the purchasing agents he has talked to in electronic companies since the President's announcement expect that this 10% surcharge will be around for a long time. But it is causing some interesting situations: "Take the switches we sell U.S. manufacturers switches that they in turn ship over to Taiwan to be assembled into their products. They know that they can bring U.S.- made components like ours back duty free, while any part they buy over there will cost them 10% extra to bring into the U.S. I think that now we will be more apt to have engineering design and component manufacture remain in the U.S., even when assembly is done offshore. Since offshore assembly labor can be dramatically cheaper than stateside labor, the 10% added to that fraction of the product might not seem too bad for the U.S. manufacturer."

"The problem with Japanese competition in components is that it gets roughest at the highest volumes-just where the real money is," said Walt Jemison, general manager at Michigan Magnetics, Vermontville, Mich. - another tape-head manufacturer that has tilted with the Japanese. "For small-volume orders-under 5000-we are only about 20% higher, and half the time the Japanese won't even bother to quote on these. But for largevolume orders-over 10,000-we are 100 to 150% higher. The Japanese can sell an eight-track automotive cartridge player head for \$0.89 while we can't go below \$1.65. Obviously, even with the 10% surcharge, they can beat us. However, I agree that the psychological aspect of the President's action will definitely help us. It ought to give courage to those few remaining stateside manufacturers of audio entertainment products, like 3M and VM in the cassette field. They, and others in similar predicaments, will continue to provide jobs for U.S. engineers."

Connector Takes Rough Treatment

Special requirements of the oil industry have prompted the development of a connector that will stand up under extreme environmental conditions.

Subterranean oil deposits are located through analysis of seismic readings obtained by detonating explosive charges in potential oil-bearing terrain. This analysis involves the use of multisection cables containing geophones that pick up seismic vibrations, transform them into electrical impulses and transmit them through the cable to amplifiers and recorders. The patterns thus recorded are then studied for indications of oil deposits.

A standard cable might consist of 48 sections, each section up to 300 feet long, interconnected with a heavy-duty connector. This is where the "RUF-NEK" connector, developed by Hughes Aircraft Company's Connecting Devices Div., Newport Beach, Calif., comes in.



Since the cables are laid on open terrain for distances up to three miles, the connectors must be capable of withstanding rough field handling and all types of weather conditions. Tests of the "RUF-NEK" show that it will remain sealed in up to 100 feet of water, withstand 3000 pounds of tension and even the load of a 39,000-pound truck. Identical halves mate with each other eliminating the need for male and female versions of the connector. With 164 contacts, it meets current and foreseeable needs of the oil industry.

Other potential uses are in mining, portable field recording and instrumentation, utilities, communications and other commercial and military ground equipment cable applications.

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New Celanex-917 is the first in the dome because of its supethermoplastic polyester to com- rior combination of electrical. bine dimensional advantages thermal and mechanical propof thermosets with processing erties. Celanex-917 also elimiadvantages of thermoplastics. nated the problems of poor It's the most processable poly- finish, cracking, poor uniester on the market. By far.

Raritan Engineering, Millville, N.J., is using Celanex-917 for machinable for a glass-reinpump components and electric forced plastic. It's rigid, won't motor domes on their new marine heads.

Just as important, Celanex-917 completely resists strong Celanex-917 was called X-917. chemical decontaminants But by any name it's a strong, mixed with sea water in the tough plastic that can do things pump. In this part Celanex re- no other thermoplastic can. Celanese Plastics Company, places brass. It replaces phe-Write on your letterhead for Dept. X-601, 550 Broad Street, nolic and polyester thermosets more detailed information. Newark, N.J. 07102.

formity, and tool wear during That's part of the reason drilling and tapping of holes.

> Celanex-917 is outstandingly crack or become brittle, doesn't distort or creep.

During development,



Celanese Plastics Company is a division of Celanese Corporation. Canadian Affiliate: Chemcell Resources, Ltd. Export: Amcel Co., Inc., and Pan Amcel Co., Inc., 522 Fifth Ave., New York 10036.



00000

Molders: A. L. Hyde Co., Grenloch, N.J., Rapid Tool & Mfg. Co., Newark, N.J.

Watch for EDN/EEE's fifth annual Caravan tour, October-November 1971. A traveling exposition of products and ideas visiting leading computer and peripheral equipment manufacturers throughout the U.S.A.

EEE MAGAZINE PRESENTS...

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EDN/EEE CARAVAN ROUTING

October 4 - November 5, 1971

DATE / DAY / TIME

Monday, Oct. 4 9:00 - 12:00 noon 1:30 - 4:30 p.m.

Tuesday, Oct. 5 9:00 - 11:30 a.m. 2:00 - 4:30 p.m.

Friday, Oct. 8 9:00 - 12:00 noon

Monday, Oct. 11 9:00 - 11:30 a.m. 2:00 - 4:30 p.m.

Tuesday, Oct. 12 9:00 - 12:00 noon 1:30 - 4:30 p.m.

Wednesday, Oct. 13 9:00 - 12:00 noon 1:30 - 4:30 p.m.

Friday, Oct. 15 9:00 - 12:00 noon 1:30 - 4:30 p.m.

Monday, Oct. 18 9:00 - 12:00 noon 1:30 - 4:30 p.m.

Tuesday, Oct. 19 12:00 - 5:00 p.m.

Wednesday, Oct. 20 9:00 - 11:00 a.m. 2:00 - 4:30 p.m.

Thursday, Oct. 21 9:00 - 12:00 noon 1:30 - 4:30 p.m.

Friday, Oct. 22 1:30 - 4:30 p.m.

Monday, Oct. 25 9:00 - 12:00 noon 1:30 - 4:30 p.m.

Tuesday, Oct. 26 9:00 - 12:00 noon 1:30 - 4:30 p.m.

Wednesday, Oct. 27 9:00 - 12:00 noon

Thursday, Oct. 28 9:00 - 12:00 noon

Friday, Oct. 29 9:00 - 12:00 noon 2:00 - 4:30 p.m.

Monday, Nov. 1 9:00 - 11:30 a.m. 1:30 - 4:30 p.m.

Tuesday, Nov. 2 9:00 - 12:00 noon 1:30 - 4:30 p.m.

Wednesday, Nov. 3 9:00 - 12:00 noon 1:30 - 4:30 p.m.

Thursday, Nov. 4 9:00 - 11:30 a.m. 1:30 - 4:30 p.m.

Friday, Nov. 5 9:00 - 12:00 noon 1:30 - 4:30 p.m.

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and

26 IC Manufacturers will conduct an IC Applications Seminar

International Hotel, Los Angeles October 5-8, 1971

Emphasis will be on application hints for maximum effectiveness . . . to help circuit and system designers select and design with new integrated circuits. The seminar will be divided into two programs: linear ICs on October 5-6 and semiconductor memories on October 7-8. Attendees may register for either one or both programs.

All of the papers being prepared for the seminar are new, dealing with fresh approaches to IC applications. The authors represent many years of experience in solving problems relating to ICs and improved circuit, system and equipment designs.

Participating IC Manufacturers: Advanced Memory Systems

Advanced Micro Devices

Analog Devices

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Electronic Arrays

 Fairchild Semiconductor
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Intersil
MOSTEK
Motorola

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Silicon General
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Teledyne Semiconductor

Texas Instruments Incorporated

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Some Participating Speakers

Bob Mammano: (left) engineering manager at Silicon General since formation of the company in 1969... was previously with ARINC Research...

Mike Markkula: recently joined Intel from Fairchild Semiconducfor where he was director of IC product marketing . . .



Merle Hoover: manager of linear Jim Bohorquez: linear integrated circuit applications products manager at Solengineering at RCA . . . has 13 itron Devices . . . was a microelectronic patents senior design engineer

Jim Bohorquez: linear

products manager at Solitron Devices ... was a senior design engineer with the Union Carbide microcircuit operation when it was purchased by Solitron in 1970 ...



Leo Cohen: manager of advanced product development at General Instrument . . . is responsible for the development of new MOS arrays . . .

Linear IC Program Speakers: Garth Wilson, Precision Monolithics; Merle Hoover, RCA; Gus Pfaehler, Fairchild Semiconductor; Bob Mammano, Silicon General; Doug Sullivan, Analog Devices; Dave Ludwig, Teledyne Philbrick; Jerry Graeme, Burr-Brown; Jack Robertson, Zeltex; Don Jones, Harris Semiconductor; Dave Fullagar, Intersil; Jim Giles, Advanced Micro Devices; Colin Berry, Signetics; Karl Huehne, Motorola; Joel Scheinberg. National Semiconductor; Wayne Folleta, Qualidyne; Jim Bohorquez, Solitron Devices; Dale Pippenger, Texas Instruments Incorporated; and others to be announced.

Semiconductor Memory Program Speakers: Marv Pollock, Unisem; Dale Mrazek, National Semiconductor; Bob Kressler, Texas Instruments Incorporated; Sven Simonsen, Advanced Micro Devices; Al Tuszynski, Solitron Devices; Bud Broeker, Motorola; Joe Rizzi, Intersil; Gordon Hoffman, MOSTEK; Leo Cohen, General Instrument; Ron Livingston, Advanced Memory Systems; Mike Markkula, Intel; H. William Slaymaker, SEMI; Dick Eiler, Electronic Arrays; George Rigg, Signetics; Vahe Sarkissian, Fairchild Semiconductor; and others to be announced.

Partial List of Linear IC Papers:

- Monolithic D/A and A/D Building Blocks
- Designing with Ultra Low-Drift Operational Amplifiers
- Fast Settling Time Amplifiers
- Designing with D/A and A/D Converters
- Applying Digital/Analog Interface Circuits
- Noise in Operational Amplifiers
- High Speed Comparators

Programs will run from 9

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- Applications for Micropower Amplifiers
- Designing with Micropower Operational Amplifiers
- Interface Circuits for Computer Systems

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Please register me for:

- □ The Linear IC Applications Program, October 5-6, 1971. Fee: \$95
- □ The Semiconductor Memory Applications Program, October 7-8, 1971. Fee: \$125
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Note: If you wish to confirm reservations by phone, call (212) 689-3250. Ask for seminar registrar, Ext. 252.

Partial List of Semiconductor Memory Papers:

- Field Programming vs Factory Programming of ROMs
- Trends in Semiconductor Memories
- New MOS and Bipolar Semiconductor Memories
- A Comparison of Various Dynamic RAMs
- Bipolar Read-Only-Memory Applications
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CIRCLE NO. 11

WHAT'S HAPPENING IN MOS

After seeing what MOS was all about in the last issue, it is time to move ahead and find out what is happening today, what is now available and what to look for in the future.

ROY W. FORSBERG, Boston Editor

In the September 1, 1971 issue of EDN/EEE ("Making Sense Out of the MOS Muddle") we looked at each technology as it is known today, defined terms and placed these terms in their proper perspective. Now we will view the MOS world today and see what's in store for the future.

Which Processes Will Survive?

This is a very important consideration for designers, and a perplexing one for semiconductor manufacturers. To be sure, no one technology is best for all applications so there should be many survivors. Of course, some super breakthrough could upset the thinking of the industry as it is today. It could make one or two processes the best for most applications, but this seems unlikely for the next 5 years at least. It looks as though a number of technologies will become standard in the years to come and be directly related to applications.

High-threshold p-channel <111> will continue for a number of years simply because of its sheer volume in the field and a certain amount of inertia. Most new designs, however, whether cost-conscious or not will use some low-threshold process because many will be costcompetitive very soon. As a matter of fact, Intel claims it can make p-channel silicon gate devices right now at lower costs, General Digital claims it can make them at the same cost and others like Electronic Arrays feel things will be equal by the end of 1971.

Low threshold p-channel <100> will not be a continuing process except as a replacement item in existing products. There are already too many processes such as nitride, ion implant and p-channel silicon gate that are cost-competitive and still offer many performance advantages. The exception here is National Semiconductor which attains high field thresholds and good performance by special processing.

The low-threshold, high-field, p-channel nitride process should become a standard for low-cost, relatively low-speed and medium density applications, and can replace both high-threshold p-channel <111> and low threshold p-channel <100> in these areas. It could be that some form of dielectric comparable in properties to nitride, but easier to handle, will come along-but the basic process will remain.

P-channel silicon gate should become the workhorse for applications requiring high density and medium power, speed and cost. As the process is refined, it will also compete in low-cost applications.

Ion implantation as a processing tool will be used in one way or another by all manufacturers within a few years. Equipment will be refined and become less costly as more suppliers move into this market. Because of its ability to adjust thresholds, make depletion devices, make CMOS devices, etc., it is too useful a tool to ignore. Circuits made by ion implantation will be costcompetitive with most other technologies and offer some performance advantages.

Complementary MOS will also be a standard for many existing and new market areas. Its low power, high speed, wide supply tolerances and high noise immunity place it in a unique position to meet many design needs that can't be solved by other technologies. Its only real competitor in some of these markets will be a single-channel ion-implant process. CMOS will find it difficult to compete with many of the singlechannel processes for use in high volume LSI arrays, except for those special needs calling for its low power, high noise immunity, wide operating voltage properties. As the process is refined further, costs could tumble and the features noted could make CMOS a close competitor for MSI and LSI bipolar arrays.

The real sleeper in this whole game could be some form of n-channel device, with silicon gate as the most likely candidate. Processing difficulties have been a real drag to this process and when they are overcome – whether by silicon gates, field shields or other means – n-channel could take over most performance-oriented applications requiring high speed, high densities and

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(Continued)

MOS (Cont'd)

PROCESS	SILICON ORIENTATION	THRESHOLD VOLTAGE	FIELD OR PARASITIC INVERSION	POWER SUPPLIES	GAIN FACTOR
High-Voltage P-Channel	<111>	3-6	30	20-30	2.5
Low-Voltage P-Channel	<100>	1,5–3	15	10-15 (often +5 & -12)	2.0
Low-Voltage/High Field P-Channel (with channel stops)	<100>	1.5–3	30	10-30	2.0
N-Channel Enchancement	<100>	0.5-2	15	5-15	6
N-Channel Field Shield	<100>	0.4-0.8	~	5-15	
N-Channel Depletion	<100>	1–4 (Pinchoff)	15	5–15	8
High-Voltage P-Channel Nitride	<111>	3-6	30	20-30	2.5
Low-Voltage P-Channel Nitride	<100>	1.5-3	15	10-15	2.2
Low-Voltage/High Field P-Channel Nitride	<111>	1.5–3.0	25	10—25	8
SATO	<111>	1.5-2.5	25	10-25	2.5
SATO Si Gate	<111>	1.5-2.5	20 (Si) 45(AI)	10-25	2.5
Low-Voltage Complementary	<100>	1.5-3 (p) 1.5-3 (n)	30 (p) 16 (n)	5–15	2.0 (p) 4.0 (n)
Ultra-Low Voltage Complementary	<100>	0.5-1 (p) 0.5-1 (n)	5 (p) 5 (n)	1—5	2.0 (p) 6.0 (n)
P-Channel Si Gate	<111>	1.5–2.5	15 (Si) 25 (Al)	10–25	2.5
N-Channel Si Gate	<100>	0.5-2	15	5-15	6.0
Low-Voltage Complementary Si Gate	<111>	1.5–2.5 (p) 1.5–2.5 (n)	25 p (Al) 15 n (Al)	5–15	2.5 (p) 4.0 (n)
Ultra-Low Voltage Complementary Si Gate	<100>	0.5–1 (p) 0.5–1 (n)	5 p (Al) 5 n (Al)	1–5	2.0 (p) 6.0 (n)
Ion-Implantation	ANY	In threshold tailoring process, typic- ally adjusted 0-3V from base process value. No change when used only for self-aligned structures	Unchanged from base process	Modified according to threshold voltage	Same as base process

relatively low costs and power.

If you look at American Micro-systems Inc., the recognized production house of the MOS industry, you will find them either in production or hard at work on almost all of the above processes. AMI is especially enthused over ion implantation as a processing technique.

The use of refractory metals in place of silicon gates offers many advantages. However, the inertia of the drive toward silicon will probably more than offset these advantages and keep refractory metals in the background.

There are still a number of processes similar to those

already mentioned but unique to a single company. To the design engineer, they are analogous to some of the other processes as far as performance is concerned and can be interchanged at will. Thus for a particular company, its own process can be the best cost/performance one and be dominant for that company. One that stands out in this category is the SATO process at Texas Instruments Incorporated. There should be no problem at all with this situation, for if all cost/performance requirements are equal, a designer shouldn't be too concerned with which process makes his circuits.

Silicon on sapphire or spinel will not be a reality for 3 to 5 years at least. There are many difficulties to overcome, among them very high cost. If problems are solved, CMOS could really take off. Most feel that today's needs, and those of the near-future, can be adequately met by current technologies without SOS. (See **Table I** for a MOS process summary.)

What to Expect in the Future

More and more MOS in plastic packages, with an attendant cost reduction, is the general byword throughout the industry. The multilevels of metal approach is also seen by many as coming. This could lead to speed and complexity gains as great as 2X in random logic and 40-50% in memories.

Collins expects to produce MOS arrays on chips as large as 250 mils on a side as a result of artwork improvements and new masking techniques.

Hughes and National Semiconductor see high V_T MOS devices in the hundred-volt ranges for driving things like gas displays. National already has as a standard product a neon driver with output capabilities to 115V.

Computer Microtechnology predicts that n-channel silicon gate circuits with depletion loads will be in volume production in 2 years. Devices will have a single 5V supply and could replace some MSI now in TTL.

MOSTEK envisions n-channel devices made by implanting positive ions in the channel until the normally depletion devices become enhancement-mode devices. They also see depletion loads making superior analog circuits which will permit the placement of high-gain amplifiers, differential amplifiers and the like on complex arrays.

Motorola also expects increased mixing of analog and digital devices on the same chip.

Solid State Scientific and Bell Labs anticipate the emergence of many forms of electron beam techniques. For example, applications could be ion-beam photoresist for greater resolution, ion back sputtering for etching (more pure) and ion implant. The significance of this is that all three are done in a vacuum, thus they are very clean and should lead to high yields.

A Word about Depletion Mode Transistors

Not too many people argue against Harry Neil of Intersil when he says that depletion load devices are the designer's dream of the future, much as current sources are used by linear circuit designers.

Depletion-mode devices are used as constant current loads for enhancement-mode drive transistors. This arrangement, similar in a sense to CMOS, makes the circuit insensitive to power supply variations, and allows internal voltage swings equal to the supply without need for a V_{GG} supply. It results in a higher speed/power product, so lower power is needed for equivalent performance. These devices also permit smaller output drivers (see **Fig. 1**) and allow linear operation.

Depletion-mode loads are currently being made by ion implantation, however Texas Instruments Incorporated and others expect to be able to do it by different



Fig. 1–**MOS Output Buffer Stage.** The output sink device must present an impedance of less than 310Ω which is a function of both device size and gate voltage. When used as R_L , an ion-implanted depletion-mode device provides a much more negative drive for the output device than that from an enhancement-mode (Si-gate) R_L device. Because of this increased drive, size typically is reduced more than 2:1–from perhaps a 130- to a 50-mil² area.

(continued)

MOS (Cont'd)

means. National Semiconductor uses circuit design tricks to get other devices to act like depletion devices, but at the expense of real-estate. The alternative to enhancement-depletion mode operation is CMOS, with a saving in power but at the cost of space.

Random Thoughts

Be careful when making a decision to use MOS for your new designs. There is a minimum level below which it is neither economical nor efficient to use custom designs. First talk to a number of vendors who can help you pick the right technology. Remember, MOS does not fit all applications efficiently.

Don't go to a vendor and specify a particular technology for your new designs. Talk to more than one, including some who have multiprocess capability. It could very well be that your design can be made cheaper and more efficiently by a process other than the one you had in mind.

Consider carefully the source for your product. It is just as important to evaluate the manufacturer's capability and reliability as it is the process. Make sure that the product is available in adequate quantities and with the qualities needed.

When evaluating different process costs, keep in mind total system costs including cost of power, PC board cost, space, clocks, drivers and decoders and the like.

If you don't need TTL compatibility, don't ask for it. By avoiding it, you may be able to end up with higherperformance, lower-cost circuits.

Be careful about picking a new, unproven, short-history technology. If you do, you'll have to compile your own performance and reliability history.

In specs, watch for guaranteed speeds rather than nominal ones. The question to be answered is: Can the

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Table II shows which processes are being used by each company.

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Mostek	f	f		f				bf										
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North American Rockwell	Most	ly cus	tom, a	ny cir	cuits	includ	ing RC	DM, RA	AM, S/	C etc.	(b,d,	.)						d MNOS or MTNS
Ragen Semiconductor						k	k									k		f 1 ² Low V _T
RCA	1	k			k	k				k				k	k			g 1 ² Self aligned gat
Signetics	bl	1	1	bl	bl	bl		1										i SATO w/silicon ga
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Texas Instruments Incorporated	hi	bdi	d	bdh	bdhi	bdh		bh	db		bd	bcd			b		b	n NMOS, stricon gat
Varadyne	j																	

device you buy drive the outside world at the required speed?

When second sourcing, it is usually best to stick with the same process. Although different processes can be used to produce many identical items and meet cer-

Many thanks are due the following companies for their valuable assistance in compiling these articles:

ADVANCED MICRO DEVICES, Sunnyvale, Calif.; AMERICAN MICRO-SYSTEMS, Santa Clara, Calif.; ARTHUR D. LITTLE, Cambridge, Mass.; BELL LABS, Murray Hill, N. J.: COGAR, Wappingers Falls, N.Y.; COLLINS RADIO, Newport Beach, Calif.; COMPUTER MICROTECHNOLOGY, Sunnyvale, Calif.; ELECTRONIC ARRAYS, Mountain View, Calif.; FAIRCHILD SEMICONDUCTOR, Mountain View, Calif.; GENERAL DIG-ITAL, Newport Beach, Calif.; GENERAL ELECTRIC, Syracuse, N.Y.; GENERAL INSTRUMENT, Hicksville, N.Y.; HUGHES. tain nominal specs, the devices can be different inside and can vary functionally in other areas.

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Bob Noyce of Intel Speaks Out On the Integrated Circuit Industry

You can probably remember back to the days when we thought resistors were cheap. I'm reminding you of that to indicate just how much change really has occurred in our industry.

There was a time when resistors were actually cheaper than transistors; some of you are too young to recall that and may find it hard to believe. In those days the basic concept in designing was to eliminate as many transistors as possible and replace them with resistors. In that era, diodes were also significantly cheaper than transistors and were popular with designers. Today, I doubt if any engineer would seriously think of replacing transistors with diodes, particularly in integrated circuits where there's really no difference in cost.

Also in those days, there was an enormous proliferation of transistor types. As a matter of fact, when the type numbers registered reached the 2N700s, it was decided to assign three-digit suffixes to small-package transistors (such as those in the TO-18 case) and four-digit suffixes to larger package transistors (TO-5 or larger cases). The idea was to keep about 300 type numbers reserved for packages that were too small to accommodate a type number with a four-digit suffix.

Once that decision was made, all new transistors in TO-18 cases received 2N three-digit numbers and all new transistors in TO-5 cases received 2N fourdigit numbers. This worked for a while, but because transistors kept coming out so rapidly the system was soon overwhelmed by thousands of type number requirements.

Even with all the thousands of 2N transistor type numbers registered, I doubt if many of you have used more than 20 to 30 of them or are presently using more than 20 or 30 different transistor types.

The number of distinct device types needed by a designer today is significantly reduced from what he needed in past years. This is because the capabilities of individual transistors now are typically far in excess of the requirements of various applications.

Audio amplifiers were designed with 100-kHz transistors in our early days, and RF transistors were operated at 5 MHz. It was considered just fine if an audio transistor got up to 20 kHz, grounded-emitter configuration. Obviously, as the capabilities of transistors have improved, the task of the designer has been simplified.

Of course, the advent of the integrated circuit was to change the life of the designer and revamp every concept of circuit and system design.

Once ICs began to appear, there was a tremendous demand from transistor users to convert their particular needs to monolithic form. I think that for every flip-flop developed by an IC manufacturer (Continued)

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Speakout

during the period from 1960 to 1964, there were customers coming in and asking for 50 other types. I remember visiting a customer during this time and going into one room where this company had 60 engineers designing logic circuits. But when I visited the same company about 3 years later, only three engineers were employed in the same group.

Now, the other 57 engineers did not all go to work for semiconductor companies; 50 of them probably moved into a higher level of design, but maybe five or six of them actually did go to work for semiconductor manufacturers doing circuit design.

The proliferation of design that took place in the early 1960s resulted in expensive solutions to design problems. It would have been a lot less costly to use fewer devices (perhaps overdesigned for those particular jobs), but thereby achieving larger production runs for each device.

If you can remember when resistors were inexpensive, then you can probably recall the days when system designers were choosing between two-input and three-input gates. If you didn't have three inputs, you used the simpler device—you never had any open inputs. Who would think of doing this today? Now it doesn't cost any more if your devices are designed in excess of actual needs for a particular application—particularly when the "excess needs" may cut down the total part count in other subsequent applications.

When you stop and think about it, the whole real appeal of integrated circuits has been their ability to cut down interconnection costs.

Look at the yield statistics. The cheapest transistor chip to make is the single transistor chip. If there's a defect in it, this means only one transistor has to be thrown out. The only reason a lot of transistors on one chip cost less than individual transistors is the savings in interconnections, both to the user and the semiconductor manufacturer.

Let's consider a circuit requirement somewhere in the middle of the user's system to be hooked up to 40 or 50 transistors within the system. For an integrated circuit, this may be accomplished by eight or ten wires; for transistors, it may call for 140 or 150 wires. That's a big difference in interconnection cost.

We've already reached what appears to be a ridiculous price situation in certain applications (for example in some TTL subsystems) where the component unit costs a fraction of what must be paid to interconnect it. The user's interconnection cost for a TTL gate can run up to \$0.50/unit-more than the cost of the gate.

Medium scale integration evolved naturally as a means for cutting the costs of building integrated circuit systems. It started out first as a custom business, but it is evolving into a catalog-item marketplace. A designer can get out his shopping list and say "Okay, I can build this circuit by using two of these and a half dozen of those or I can use three of these with four of those", and so on. Put them all together, they accomplish the desired function and you don't really even have to worry about what's inside or the fact that they can do a lot more than you need to have done. Not only will these standard circuits do what you require, they're as cheap a way as any to get it done.

We've been talking about MSI but we haven't really left the subject of interconnections. Remember, it's the cost of interconnection that was the prime motivation to the evolution of MSI.

This leads us to large scale integration, where the motivation for development has been precisely the same-lowering interconnection costs. It may not be true right now but the time will come when the cost of MSI will become lower than the cost of the boards that it goes on. And today, the interconnection cost for MSI is still significant when compared to the cost to duplicate the same job with LSI.

Again, LSI has started out primarily as a custom business. Most of the LSI products that have been sold have gone to calculator manufacturers – calculators are one place, indeed, where there is large volume usage of a relatively well-standardized circuit. For more achievements of this type, standard LSI circuits must have enough capability to do the desired job and a lot of other jobs as well.

Memory is a good example of an application well suited for standard LSI. The function is well defined, the usage is large and one design can satisfy many different needs.

LSI memories are being proven practical production items. In 1968 and even in 1969, a lot of skeptics said that LSI was at least 5 years away-LSI was something that the IC manufacturers liked to pretend was around the corner, but you wouldn't be able to buy any for at least 5 years.

But LSI did arrive and is available in large quantities. The IC user today is in a position where he can count on LSI deliveries of his design in volume.

Of course, the user still has the problem of getting

the design done, and simplification of that problem still has a long way to go. Even with all the automation that has gone into laying out logic circuits, these techniques still can't do the LSI job very well - the individual is a little slower than the computer but it's not possible to do the job cheaper by computer than by hand. The automated approach isn't the answer right now either, unless you're willing to give up something both in production cost and performance of the unit. We're continuing to push ahead but right now most design problems are being worked out by hand.

Back in 1964, Gordon Moore said that in 1971 designers would be able to buy ICs with more than 1000 components in high quantities. In 1965, that sounded to a lot of people like a daydream.

If you look seriously at the way IC technology is moving today, you can extrapolate and come to the conclusion that ICs with one million components will become available in 1980.

This sounds ridiculous but actually it's no more ridiculous than 1000 components on a chip sounded in 1964.

If IC technology really moves along at this pace, what will happen to prices? IC prices have been affected by several factors – increased complexities, improved resolution, improved yields, greater wafer sizes, etc. Increased die sizes have allowed more function per individual die and lower handling costs. Let's see what prices are likely to be by 1980.

One of the big cost factors in the semiconductor business is defect density, which has gone down by a factor of six in the last 10 years. Correctly anticipating the behavior of defect density is one of the critical factors in extrapolating to what will happen in 1980.

The \$10/square-inch cost of processing silicon, about where we are now, is probably not going to change much. In order to decrease defect densities, it's going to take even more careful processing than we're now doing, and we aren't going to save much money. I'm also assuming that we will be able to decrease defect densities, since there's nothing inherent in semiconductors that makes it impossible. Most of the defects that are present in integrated circuits are process induced defects-defects that exist only because of mistakes that IC manufacturers make.

It isn't a question of achieving the ultimate in

crystal perfection. It's just a question of how dirty your photoengraving operation is, and frankly, that's the cause of 90% of the defects in ICs right now.

In looking to the future, I'm assuming that we'll improve our linear resolution by a factor of three. That's about where I see the industry going from an optical standpoint. We can't go much beyond that until we get into electron-beam processing. I do believe that electron-beam processing will come in before the end of this decade.

I have also assumed that we will see an improvement in efficiency. By that I mean circuit configurations will be designed that will provide more function per circuit element. New device concepts such as the charge-coupled device will enter the picture.

Okay, let's look at the chips IC makers will offer in 1980. The size of the MOS chip will be larger than the bipolar chip because the MOS defect density will be smaller. Why will it be smaller? Because the MOS process uses fewer photoengraving steps, and photoengraving is the major cause of defects.

Typically, we'll be working with 1.5 cm^2 of silicon for MOS circuits, and 0.6 cm^2 for bipolar circuits. Chip cost should be running around \$3 for bipolar circuits and \$9 for MOS circuits. That's with yield consideration included and estimated at 30%. (If this yield figure is too low, the cost figures that I'm giving you will be too high.)

The number of components per chip will be about one million MOS devices and about 100,000 bipolar devices. If 10 components per memory bit are assumed, then one order of magnitude less bits than the number of components can be obtained.

Let's assume that the cost of packaging is \$10. Let's also assume that we only get 50% yield after packaging (and that number shouldn't be that bad).

With these projections, it's likely that the cost of MOS memory will be \$0.0003/bit and bipolar cost will be a little under \$0.002/bit. To arrive at these costs, I've assumed a 50% cost of sales for the semiconductor companies.

I've based the above figures on semiconductor memory growth; all the technologies involved are applicable to logic as well as memory. However, with logic, we are getting into a different situation.

Interconnections again are a severe problem. We find ourselves interconnection-limited. How much logic can we conceive of putting on one chip? How many gates will be needed for minicomputers? Since the answer for some minicomputers is 1000, by 1980 we may well be capable of putting the equivalent (Continued)



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number of gates for 100 minicomputers on one chip.

A big part of the minicomputer market calls for gate requirements in the 5000 range; bigger computer needs run say 30, 40, 50 and up to 100,000 gates. The biggest computers made today have requirements in the 100,000-gate range. This would make it sound as if a superstar computer's needs could be satisfied with about 10 bipolar LSI chips. However, even if the capability exists to put all of a computer's logic on a few chips, this doesn't mean that we'll be able to find a practical design philosophy that will permit us to do it — and that brings us back to the whole interconnection problem again. \Box

About Bob Noyce

Dr. Robert N. Noyce was one of eight employees who left Shockley Semiconductor Labs in 1957 to form Fairchild Semiconductor. He served as Director of Research of the fledgling Fairchild operation, placing major R&D emphasis on mesa and planar silicon transistors.

He became vice president and general manager in 1959, three years before Fairchild Semiconductor became a part of Fairchild Camera & Instrument. Dr. Noyce was appointed Group Vice President for the semiconductor and instrumentation divisions in 1965, a post he held until leaving in 1968. In July 1968, he founded Intel Corp and has served since then as its president.

Dr. Noyce received a bachelor's degree in 1949 from Grinnell College in Iowa, majoring in physics and math. He earned his doctorate in physical electronics at MIT in 1953.

Upon graduation he joined Philco Corp. in Philadelphia, Pa., engaging in semiconductor research. He left Philco to join Shockley Semiconductor Labs in 1956, where he was concerned primarily with research in semiconductor diffusion techniques.

Dr. Noyce finds time for skiing at Squaw Valley and sailing off the Maine Coast. "We have six boats – if you want to count the row-boat – one for each member of the family," he says.

The family consists of Bill 17, Penny 15, Polly 12, Margaret 10 and Betty, Dr. Noyce's wife. They reside in Los Altos, Calif., and also have a seashore home in Maine.

Dr. Noyce is a member of the National Academy of Engineers, a Fellow of the IEEE and a Trustee of Grinnell College.

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Designing Precision Integrators With High Speed Mode Controls

by Paul Yee

• The problem of capacitance drift with temperature is well known in the analog electronic integrator. Not so well known is the mechanical drift in the adjustable capacitor favored in these integrators.

Mr. Yee details a method of minimizing capacitance drift and replacing the adjustable capacitor with a fixed type by using additional circuitry. \blacksquare

A new integrator circuit has several advantages over "standard" integrators:

1. The feedback capacitor is calibrated and temperature compensated actively, removing the dual requirements of a regulated temperature chamber and adjustable capacitor. In addition, the fixed capacitor offers improved long-term stability as well as a simpler initial calibration procedure.

2. Large variation of the time scale is possible without a variable capacitor.

3. All-solid-state switches give improved reliability, reduced package size, and submicrosecond mode switching which allows close tracking of mode change among multiple channels of integrators.

The integrator is one of the most commonly used circuit configurations in analog computation, system simulation, in-line process control, etc. The basic components used in an integrator are a solid-state operational amplifier, a feedback capacitor and switching components.

During recent years, the quality of op amps and solid-state switches has improved im-

Author: Mr. Yee is product manager at Zeltex in Concord, Calif.

mensely. However, the performance of capacitors remains essentially unchanged. Today's precision integrators still use yesterday's polystyrene capacitors.

To maintain initial tolerance and temperature stability of, say $\pm 0.01\%$, the polystyrene capacitor must be installed and operated within a well regulated temperature environment. Setting an adjustable capacitor to a desired value can be very time consuming since the device requires quite a long period to establish mechanical equilibrium.

Conventional integrators

In general an integrator has the following functional modes: "operate", "reset", and "hold". These modes can be established by some combination of FET, biopolar, and mechanical switches. For the "hold" mode, a solid-state switch should have a low "on" resistance and an extremely low leakage current. Neither FET nor bipolar units can provide these, so mechanical switches have hitherto been used exclusively in this mode. But a mechanical switch's slow response in the "hold" mode can cause computational error in multiple integrators.

Before we analyze the new integrator, let's examine two conventional precision integrators. In Fig. 1 we use only mechanical switches, while Fig. 2 has solid-state switches with the exception of SW_i . Both circuits suffer from common deficiencies caused by the mechanical "hold" switch and the limitation of the adjustable feedback capacitor. Also, the circuit of Fig. 1 has limited reset speed due to the time constant of RC_i .

Improved circuit

Figure 3 shows a high-speed precision inte-
grator with all MOS FET switches to control operating modes. The feedback capacitor is a fixed-polystyrene type. Initially, the capacitor is set by adjusting the attenuator preceding amplifier A_2 , connected as a unity-gain noninverting buffer. No temperature chamber is needed as the capacitor's temperature coefficient is compensated by the thermistor network which regulates the attenuation of P_i . In this circuit, for (R_i) $(C_f) = 1$ second, $R_i = 100 \text{ k}\Omega$ and $C_f^* = 10.1 \text{ uF}$ at 25°C, P_1 is set to deliver 0.990 e_o .

The circuit of Fig. 3 is used as follows: In the "operate" mode, SW_1 , SW_2 , and SW_3 are as shown. In the "reset" mode, SW_1 , SW_2 , and SW_3 take on the opposite positions. In the "hold" mode, SW_3 is as shown, and SW_1 and SW_2 are in the same position as for "reset".

Figure 4 shows a practical circuit in the "operate" mode. In this mode, the desired equivalent capacitance and time scale of the integrator are adjusted by R_s and the temperature compensation of the capacitor is set by R_c and P_A .

Time constant adjustment

The desired time constant of the integrator is R_iC_f as noted in Fig. 3. However the added



Fig. 1. Three-mode integrator using only mechanical switches.



Fig. 3. High-speed precision integrator with MOS FET switches.

circuitry takes a slightly larger feedback capacitor C_f^* equal to C_f (1+ Δ) to produce the desired equivalent C_f (at 25°C). To adjust the physical capacitance C_f^* to the desired equivalent value (C_f), a precision attenuator consisting of a buffer amplifier and resistive network preceding C_f^* is employed.

With input current, i_i , to C_f^* , the impedance transfer function of Fig. 4 is adjusted to $1/sC_f$ with R_s . For $R_X = R_B$ and $R_C = R_D$ at 25°C, e_A is made equal to e_B or $e_o (C_f/C_f^*)$. For correct impedance transfer characteristic, R_s is adjusted such that:

$$\begin{pmatrix} \frac{R_C}{2R_S + R_X + R_C} \end{pmatrix} e_o = \begin{pmatrix} \frac{R_D}{2R_S + R_X + R_D} \end{pmatrix} e_o$$

$$= \begin{pmatrix} \frac{C_f}{C_f *} \end{pmatrix} e_o = \frac{i_i(s)}{sC_f *}$$

$$or \frac{e_o(s)}{i_i(s)} = \frac{1}{sC_f}$$

$$(1)$$

Temperature-coefficient compensation

Over the normal lab temperature environment, the temperature coefficient of fixed polystyrene capacitors is linear and typically $-0.01\%/^{\circ}$ C.



Fig. 2. Three-mode integrator using two solid state and one mechanical switch.



Fig. 4. Prototype circuit in the "operate" mode with $R_x = R_T R_A / R_T + R_A$, $C_f^* = (1 + \Delta)C_f$, $R_c = R_D$ and $R_x = R_B$ at 25°C.

To compensate this linear change of capacitance over the range of +15 to $+35^{\circ}$ C, a thermistor of the proper negative temperature coefficient is introduced into the attenuation network. To linearize the exponential effect of the thermistor, a temperature-stable resistor, R_A , is added in parallel with the thermistor, R_T . The following equations describe R_T and R_X , the parallel resistance of R_T and R_A .

$$R_T = R_{T_o} e^{\beta} \left(\frac{1}{T} - \frac{1}{T_o} \right)$$
(2)

$$R_{X} = \frac{R_{A}R_{T}}{R_{A} + R_{T}} = \left[\frac{R_{A} + R_{To} e^{\beta} \left(\frac{1}{T} - \frac{1}{T_{o}}\right)}{R_{A} + R_{To} e^{\beta} \left(\frac{1}{T} - \frac{1}{T_{o}}\right)} \right]$$
(3)

$$\frac{dR_{X}}{dT} = -\left[\frac{\left(\frac{R_{A}^{2}R_{To}}{T^{2}}\right)e^{\beta} \left(\frac{1}{T} - \frac{1}{T_{o}}\right)}{\left(R_{A} + R_{To} e^{\beta} \left(\frac{1}{T} - \frac{1}{T_{o}}\right)\right)^{2}}\right]$$
(4)

Given R_{T_0} , T_o and β , and dR_X/d_T , R_A can be calculated from Eq. 5 as follows:

$$\begin{array}{c|c} R_{A} \\ T = T_{o} \end{array} = \left(\sqrt{\frac{-dR_{x}}{dT}} \right) \left(TR_{To} \right) \\ \hline 1 - \left(\sqrt{\frac{-dR_{x}/dT}{R_{To}\beta}} \right) T \end{array}$$
(5)

For example, let's take a thermistor of Fenwal C curve with $\beta = 3495\pm175$, $R_{To} = 7.680$ k Ω at $T_o=298$ °K (25°C). For a dR_X/dT of -50 ohm/°C, R_A calculated from Eq. 5 equals 5.480 k Ω . Further calculation of R_X over the temperature range of 25°C ±10°C using these data and Eq. 3 yields a dR_X/dT of -50 ±1 ohm/°C.

To maintain close to linear attenuation, C_f^* should not exceed C_f by 1% so that,

$$\frac{R_c}{2R_s + R_x + R_c} = \frac{1}{1 + \Delta} \tag{6}$$

can be approximated to within 0.005% accuracy by $(1 - \Delta)$. Since

$$\frac{1}{1+\Delta} = \frac{R_c}{2R_s + R_c + R_x} = \frac{1}{1+\left(\frac{2R_s + R_x}{R_c}\right)}$$

then $(1-\Delta) = 1 - \left(\frac{2R_s + R_x}{R_c}\right)$
or $\Delta = \left(\frac{2R_s + R_x}{R_c}\right)$ (7)

The term $\frac{1}{1+\Delta}$ can be made linear over 25°C ± 10°C to within ± 2% of the tr of the polysty-

10°C to within $\pm 2\%$ of the tc of the polystyrene capacitor, if dR_x/dT is linear within $\pm 1\Omega/°$ C.

Integrator time scale change

The time scale of an integrator is related to $K_2C_f^*$ (C_f/C_f^*) where K_2 is the closed-loop gain of A_2 . For a fixed value of C_f^* , a large vari-

ation of time-scale changes can be realized by merely controlling the closed-loop gain of A_2 or the attenuation of P_1 . For K_2 equal to greater than unity and still maintaining a ± 10 -V fullscale integrator output, A_2 must have an output voltage range greater than ± 10 V. For a slower time scale, higher value capacitance can be simulated using an amplifier (A_2) of a higher voltage output.

"Hold" and "reset" mode

With SW_i , SW_2 and SW_s set for the "hold" mode, C_f^* is connected across the feedback of A_2 . The voltage across C_f^* remains essentially constant as long as the input current to the inverting terminal of A_2 is negligible. Meanwhile the input current through R_i is absorbed by the low closed-loop output impedance of A_2 . The signal at the output of A_1 due to $e_i(s)$ in the "hold" mode, is approximately equal to $(e_i(s)R_o/K_2(s)\alpha_1R_i)$ where R_o is the open-loop output impedance of A_2 , α is the attenuation of P_1 and $K_2(s)$ is the closed loop gain of A_2 at the frequency of interest.

With Fig. 3 in the "reset" mode, the integrator's initial-condition voltage is set by the overall feedback around A_s , A_z and A_1 . The time required to set an initial condition is a function of the current capability of A_s , A_z , SW_z , SW_s as well as the capacitance of C_f^* .

Critical amplifier and switch characteristics

Amplifier A_1 must either be chopper stabilized or have low voltage drift. A_2 requires a FET input with high output-current capability. A_3 should be a general-purpose amplifier with high output capability.

The two important parameters of the MOS FET switches used in this application are on impedance and leakage current. The improved circuit minimizes the effects of both.

In the "operate" mode, the on impedance of SW_1 is not critical since it is inside the feedback loop of A_2 . SW_1 must be able to pass the maximum integrand current without saturating A_2 . The other two switches are in their "off" state in this mode. The leakage of SW_3 is absorbed by A_2 with negligible error, but the leakage current of SW_2 causes an integrand error.

In the "hold" mode the on impedance of SW_2 connects the feedback capacitor across A_2 as well as passing the integrand current from R_i to the output of A_2 . SW_1 and SW_s are in the "off" state and their leakage currents cause C_f *'s charge to change, causing an error at the output of A_1 directly proportional to time and inversely proportional to C_f *.

In the "reset" mode, the on impedance of SW_2 and SW_3 limits the maximum charge current to the capacitor during the initial phase of the cycle. The on impedance of SW_3 and C_f^* determine the reset time constant once A_2 resumes the linear mode of operation. The leakage current of SW_1 is of no consequence in this mode.

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Switching Regulator Designed for Portable Equipment

Here's an IC switching regulator for portable equipment that lets the battery voltage fluctuate over a wide range with no performance degradation. It's all done with low-cost components, too.

EUGENE R. HNATEK and LARRY GOLDSTEIN, National Semiconductor Corp.

Most batteries used in portable field equipment exhibit considerable voltage changes over their discharge cycle. Thus, for the equipment they power to function properly, it is generally necessary to make frequent adjustments with a series rheostat. This way of regulating voltage is inefficient and bothersome—and it shortens battery life.

A circuit was developed that uses an IC voltage regulator in a switching mode (see boxed information) to provide a highly efficient regulated supply voltage. This circuit (**Fig. 1**) makes use of the LM376N positive voltage regulator. It has a maximum output current rating of 25 mA (without external pass transistors), operates from an unregulated input voltage from 9 to 30V and provides load regulation of 0.3%.

This switching regulator combines high efficiency with a unique pluslow cost. Normally, switching regulators require fast-switching diodes and transistors, and a core (choke) with a sharp saturation characteristic to minimize losses. The approach presented here works at relatively high efficiency (87%) yet does not require fast components or sharp saturation cores. Instead, almost any diode, transistor and choke can be used efficiently. In fact, an inexpensive Japanese transformer secondary can be used for the choke, which points up the circuit's low cost, versatility and performance.

Also, the high switching frequency (50 to 100 kHz) generates transients that could be troublesome. However, because of the inherent design of the LM376N (for voltage breakdown ratings of the integrated transistors) and selective filtering employed, spikes are not a problem.

In this circuit (Fig. 1), the output



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voltage need only be set once during the design stage (not every time that the battery voltage decreases). R1 and R2 set the output voltage anywhere between 5 and 27V. A 10-k Ω rheostat was used for R1, though normally a fixed resistor is used. Values for R1 and R2 are obtained from the formulas:

$$V_{out} = 1.72 \frac{R1 + R2}{R2} V$$
$$R1 \simeq 1.11 V_{out}$$

 R_{sc} determines the base drive for switch transistor Q1, providing it with enough drive to saturate it with maximum load current. The value of R_{sc} is obtained from

$$R_{sc} = \frac{325 \text{ mV}}{I_{sc(mA)}}$$

where I_{sc} = short current limit.

Positive feedback at the reference terminal stems from R3, C2 minimizes the output ripple and C3 removes fast risetime transients that would otherwise be coupled into pin 5 through the shunt capacitance of R3. However, C2 must be small enough so that it does not integrate the waveform.

The optimum switching frequency for these regulators has been determined to be between 20 and 100 kHz. At lower frequencies the core for L1 becomes large, and at higher frequencies switching losses in Q1 and CR1 become excessive. A switching frequency of 33 kHz was selected for the circuit of **Fig. 1**.

The regulator was used to drive a (Continued)

Regulator (Cont'd)

6V, 500-mA tape recorder motor. The input voltage was varied from 7 to 20V without any change in motor speed. Furthermore, the load was varied from 700 mA of starting current to 250 mA of running current, and the output voltage of the regulator remained at 6V. In fact, stalling the motor did not cause any regulating damage (700 mA).

A New Circuit

The regulator circuit of **Fig. 1** is optimized in terms of efficiency and switching waveform, but not for the



SWITCHING REGULATORS REVIEWED

Efficiency is the main advantage of a switching regulator over the conventional series type. When compared to series regulators, switching regulators permit the use of smaller components and heat sinks to provide a specified output power capability.

The basic configuration of a switching regulator is shown below.



Regulation is achieved by controlling the duty cycle of Q1.

Transistor Q1 serves as a switch and is either on (saturated) or off, so that power dissipation in it is minimum. Freewheeling diode CR1 conducts during the time that Q1 is cut off, thus maintaining current flow through inductor L1. When Q1 is on, the load current i_L through L1 increases according to the relationship.

$$E_{in} - E_{out} = L1 \frac{(\Delta i_L)}{(t_{on})}$$

This current flows through the load and charges capacitor C1. When E_{out} reaches V_{ref} a voltage comparator turns Q1 off. Current through L1 then decreases until CR1 is forward biased. At this point the inductor current flows through CR1 decreasing at a rate given by

$$E_0 = L1 \frac{(\Delta i_L)}{(t_{off})}$$

When the inductor current falls below the load current, C1 begins to discharge and E_{out} decreases. When E_{out} decreases to slightly less than V_{ren} the comparator turns Q1 back on and the cycle repeats itself.

The output voltage is given by

$$E_{0} = \frac{E_{in} \times t_{on}}{t_{on} + t_{off}}$$

A number of precautions should be observed with all switching regulators. These are:

 Fast switching diodes and transistors must be used to prevent excessive power dissipation.

- The core material used for L1 should have a soft saturation characteristic. This prevents high peak currents from occurring in the switching transistor if the output current becomes high enough to run the core close to saturation.

 $-\mathrm{Q1}$ should have a low emitter-base saturation voltage to prevent excessive power dissipation.

-CR1 should be returned to ground separately from the other parts of the circuit to prevent large transients from occurring in the circuit.

minimum number of components. The next step, therefore, was to reduce the number of components but leave circuit performance unchanged (Fig. 2).

Almost any type of choke can be used for L1, which gives a significant cost savings. Diode CR1 can be any diode (even a low-frequency type) that can handle the actual load current, and transistor Q1 can be any variety of transistor as long as it can handle the load current and remain within its maximum ratings. Even though the boxed information recommends the use of a fast switching diode, a low-frequency diode will work in the circuit of **Fig. 2**. Efficiency of this circuit relative to input voltage is shown in **Fig. 3**.

Applications for this type of regulator are numerous. It can be used for devices powered from 9, 12 or 18V batteries, or in fact, from any battery in the range of 9 to 30V. Portable instrumentation, motor speed control for radio-controlled boats and portable tape recorders-all are promising applications of this circuit. It should be noted that for most tape recorder applications, a resistor is used in series with the tape drive motor to set the motor voltage. During starting conditions this resistor drops more voltage than when running-the motor needs high starting current. With this IC switching regulator the output voltage is independent of the load current. \Box



Both Eugene Hnatek (L) and Larry Goldstein (R) have been with National Semiconductor for 2 years. Hnatek is Military/Aerospace Product Manager, responsible for direct linear, digital, hybrid and MOS military product efforts.

Goldstein is Linear IC Testing Manager, responsible for software and hardware developments for testing op amps, regulators, consumer and communications circuits.

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Plagued By Triac Hysteresis?

Hysteresis or snap-on in triac phase control circuits is a common problem usually solved by adding components to the triggering circuit. A new IC trigger does the job neater and cheaper.

ROY W. FORSBERG, Boston Editor

Designers of ac phase control circuits are usually bothered by hysteresis or snap-on effects of simple trigger circuits (**Fig. 1**). Although they desire a smooth transition from full OFF to full ON, what they usually get is a step-type snap-on action as illustrated in **Fig. 2**. This can be very disconcerting in lamp dimmers and motor speed controls for example, and solutions such as those shown in **Fig. 3** are often employed. Such solutions are required regardless of whether the actual trigger device is a neon lamp or a bilateral switch. Unfortunately, these solutions require added discrete parts resulting in greater volume and higher costs, conditions not compatible with lamp dimmers and power tool controls.

IC trigger devices have been tried in the past but because of manufacturing constraints, such as triple diffusions needed to gain isolation, costs have not been competitive with discrete solutions. What is desired is a triggering device with asymmetrical voltage characteristics to compensate for the undesired phase shift described in Fig. 2. A simple zener-bilateral switch arrangement provides these characteristics, but when integrated on a single chip, it either requires lots of area or additional diffusions. However clever circuit design can offset these problems and result in a small, low-cost IC providing characteristics shown in Fig. 4 and per-



Fig. 2 – Waveforms showing hysteresis effect. Initially, capacitor voltage lags line voltage by about 90° and no triac triggering occurs. As resistance is decreased, this phase relationship changes until the triac first triggers at point 'x'. However, after the first triggering, the charge removed from the capacitor by triggering causes the phase angle to shift further and thus apply more power to the load as at 'y' causing an apparent 'snap-on'.

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formance shown in Fig. 5. Fig. 4 shows how both threshold triggering and conducting voltages in the negative quadrant are drastically altered in order to compensate for normal phase shift while maintaining a constant threshold current to the triac.

This IC approach results in a single trigger device no larger or more ex**Design Ideas**

SHADED AREA INDICATES LOAD VOLTAGE

pensive than conventional devices, yet requires no additional circuitry to combat hysteresis or snap-on. It is mounted in a TO-98 plastic 2-lead package.

This device was presented in a paper at ISSCC '71 by W. H. Sahm III of General Electric Company.



ASYMMETRICAL SWITCH CHARACTERISTICS

ASYMMETRICAL SWITCH TRIGGER CIRCUIT WAVEFORMS

DECREASING R

Fig. 4-IC trigger characteristics. By increasing the negative trigger voltage and conducting voltage, the dc value of capacitor voltage is shifted thus preventing any phase shift after first triggering.



Fig. 5-Circuit performance. The simple control circuit shown at the left using the new IC trigger gives close linear performance from about 3% to over 99% of the available power.

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Readers have voted William C. Schaefer and Dale B. Chapman winners of the June 1 Savings Bond Award. Their winning circuit design is "Low-Cost, Long-delay Timer." Mr. Schaefer and Mr. Chapman are with IBM Corp., San Jose, Calif.

Proportional oven-temperature controller

To Vote For This Circuit Circle 161

by Robert L. Wilbur Southwest Research Institute San Antonio, Texas

This circuit provides proportional temperature control of an oven to within 1° C for temperatures from 75 to 250°C. The circuit uses an IC voltage regulator, Type 823D, which has a quiescent current of 1.5 mA. This particular IC operates well on the same 28V power source as the oven.

Bridge resistors R_1 and R_2 should be 1% carbon-film versions. To achieve adequate resolution of the temperature setting, the potentiometer should be a ten-turn wirewound type. Since the power transistor Q_1 operates either saturated or almost cut off, no heat sink is required and operational power derating is unnecessary.

The same basic circuit can be used to control temperatures over other operating ranges, and can be easily modified by selecting a suitable thermistor and bridge resistors. Ovens of different power ratings than indicated can be controlled by suitable selection of components R_3 (to provide the correct current drive), CR_1 and Q_1 .

Low-power heater elements (where

heater current does not exceed 15 mA) can be driven directly from the output (pin 6) of the regulator IC.

This circuit was developed in conjunction with the NASA-sponsored Technology Utilization Program, Contract No. NASW-1867. □



IC which operates off the same 28V supply as the oven.

Adjustable rectangular-wave oscillator interfaces with IC logic

To Vote For This Circuit Circle 162

by David E. Manners Vision Laboratories, Inc. Oriskany, N.Y.

With this inexpensive rectangularwave oscillator, the frequency can be adjusted over a wide range and the oN and OFF times of the signal can be independently manipulated. The circuit requires only 5V dc for operation and can therefore operate from conventional logic power supplies. Because the current drain is only about 8 mA, the circuit can also be operated from a zener regulator fed by a higher voltage supply line.

Output levels of the oscillator are compatible with conventional IC logic. The circuit was originally developed to provide an input to a driving stage for low-frequency pulsing of an inductive load.

Another useful feature is that terminal 2 of the IC can accept logic signals which serve as an ON/OFF control. When held at logic 0, pin 2 forces the output to be a steady logic 1. If a steady logic-0 output is desired, another NAND gate on the same IC must be used. Removal of the logic 0 from pin 2 allows oscillation to occur. For normal operation, pin 2 is either open circuited or, preferably, connected to 5V dc.

Operation is fairly straightforward. When power is first applied, the SCR is nonconducting. Thus, pin 1 of the IC is presented with a logic-1 level. Pins 3 and 4 are therefore at logic 0. Pin 6, in turn, starts out in a logic-1 condition. This allows C_1 to begin charging from the voltage source via R_2 and R_3 , in an attempt to reach a voltage level determined by the divider network formed by resistors R_1 , R_2 and R_3 . Thus, as the voltage level increases, the SCR is eventually triggered into conduction.

When the SCR starts to conduct, a

logic 0 appears at pin 1 of the IC. This causes pins 3 and 4 to go to logic 1, and pin 6 becomes logic 0. The "near ground" on pin 6 causes C_1 to commence discharging through R_2 and also via R_1 and the gate-cathode path of the SCR. The capacitor voltage then decreases until the SCR is again cut off. This occurs because the current through the SCR is limited by R_4 and is always less than the required holding current. After the SCR stops conducting, the operating cycle repeats as described.

The table shows typical frequencies and duty cycles for selected values of C_1 , R_2 and R_3 . Note that there is a lower limit to practical values for R_3 (6 k Ω in this case) because otherwise the current-sinking capability of the IC NAND gate would be exceeded. Possible values of R_2 and R_3 are limited at the high end by the required gate voltage needed to turn on the SCR.

Total component costs for the circuit shown were about \$8, with the SCR (at \$5.75) contributing the bulk of the cost. Suitable SCRs can now be obtained for around \$2, thus reducing the total parts cost to approximately \$4.25. \Box



Both the frequency and the mark-space ratio of the output can be determined by suitable choice of component values in this oscillator.

C ₁ (μF)	0.05	0.1	0.5	10.0	40.0	R ₂ (Ω)	R ₃ (Ω)	Approx. % ON
	22.2 k	6.84 k	1.67 k	58.3	17.23	1 k	27.0 k	35
Fred	23.6 k	8.62 k	2.08 k	75.7	22.00	1 k	13.5 k	45
(Hz)	27.8 k	10.00 k	2.50 k	91.0	26.00	1 k	7.3 k	55
	7.8 k	3.92 k	0.96 k	31.2	9.26	2 k	27.0 k	45
-	11.9 k	6.25 k	1.54 k	52.1	15.15	2 k	7.3 k	60

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cover

Microprogramming cover art, supplied by Datapac, Inc., shows a section of braided U-core memory. See article on p. CH 9.

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10 new ways to improve system performance

MECL 10,000 means optimum performance

MECL 10,000 improves your system performance 10 ways — actually 16 when you consider devices previously introduced. This new "systems-oriented" logic family combines high speed (typically 2.0 ns propagation delay per gate), with low power (25 mW dissipation per gate), yielding the best speed/power combination available today.

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MECL 10,000 (of course)

MECL 10,000 – a comprehensive family

Originally designed as a computeroriented logic family, MECL 10,000 also offers the optimum combination of parameters and flexibility required for high-speed digital communications, telemetry systems, and instrumentation. In addition to these 10 functions, here is a look at the line.

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MC10131 Dual D Flip-Flop MC10181 4-Bit Arithmetic Unit

These functions will be added in 1971:

Memory Elements

MC10133 Quad D Latch MC10134 Dual D Latch W/2D Inputs & Select MC10135 Dual J-K Master Slave Flip-Flop MC10136 4 Bit Universal Counter MC10139 256 Bit Fusible Link ROM MC10140 64 Bit RAM MC10141 4 Bit Universal Shift Register

Line Receiver

MC10116 Triple OR/NOR



MC10121 4-Wide OR-AND/OR-AND-INVERT Gate — Another system oriented building block providing the simultaneous OR-AND/OR-AND-INVERT function, a natural for data distribution applications.

Complex Functions

MC10160 12 Bit Parity Checker/Generator MC10164 8 Line Multiplexer With Enable MC10179 Look-Ahead Carry Block MC10161 Three Bit Decoder w/two Enables MC10162 Three Bit Decoder w/two Enables

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MC10130 Dual Latch — A clocked dual D type latch. Each latch may be clocked separately by holding the common clock in the low state, and using the clock enable inputs for the clocking function.

MECL 10,000 eliminates the alternatives. The proof is in the comparison!





under new management - a computer -



Recently Varian Associates formed a new division that will manufacture and market a new concept in data systems – computers for the hotel and lodging industry. Already Varian/TALIX has installed a system in the 500-room Hyatt House Hotel in San Jose, Calif. Using a specially developed logic unit, room status is automatically indicated and a minute-by-minute house count of vital data involving occupancy, reservations and check-outs yet to depart is provided. Until now, to disseminate such information was too slow and inaccurate for the modern hotel. Occasionally, these inaccuracies and time lags provoked a whole variety of events that resulted in a nightmare for both customer and manager.

The new system keeps track of all information; it remembers and displays each status report until told to change the status. Each hotel requires a special logic unit. The programs are "hard-wired" and sealed—it is never necessary for hotel personnel to be concerned with this "hands off" feature. The system functions with information received from specially-designed portable data input stations.

Simplicity is the key. The new system is designed to be used by anyone, including non-English-speaking people, and is as simple to operate as an ordinary AM radio.

all a computer needs is an education –



Experiments aimed at giving the computer some of the sensory abilities of humans are being conducted at the Massachusetts Institute of Technology. These experiments make use of an electronic device called a data tablet, manufactured by GTE Sylvania Inc., a subsidiary of General Telephone and Electronics Corp. According to Prof. Nicholas Negroponte of MIT's School of Architecture and Planning, the processing abilities of today's computers are severely limited because they receive information from the real world through so few media or "senses." The goal of this research is to broaden the computer's abilities and enable it to grasp entirely new sets of ideas and concepts.

In addition to the data tablet, the experiment involves two minicomputers and a display tube. Any design sketched on the tablet is transmitted into the computer. A key feature of the data tablet is its transparency, which permits the user to mount the tablet in front of the display and compare the two drawings.

"It has been possible for years to feed drawings into computers via data tablets," said Prof. Negroponte, "so long as the sketches were exact. But we are teaching the computer to interpret data not explicitly stated. The machine must handle sketches that include hastily-drawn lines, inaccuracies, crossedout mistakes and ambiguities stemming from discrepancies between the user's intention and his execution."

As an example, if the user hastily sketches a wall with wobbly lines, the computer realizes that he probably meant them to be straight and corrects the error. If he slowly and deliberately draws a round wall, the computer assumes that the roundness is intentional. "The computer will no longer require the user to be any more exact with it than he is with another human," Prof. Negroponte continues. "This improvement in the computer's vision will enable it to comprehend pictures it previously could not. We are working toward the day the computer will be able to hear and see the world as we do. We look forward to computers with artificial intelligence that enables them to be as innovative and creative as man."

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go from Software to hardware in one easy lesson

Through "microprogramming", an instruction can be tailor-made to a specific machine. In this way, operational sequences are encoded in hardware and the instructions are executed more rapidly.

Instead of hardwiring a function, use a read-only memory (ROM) to store the routine that performs the function—an intermediate step between software and hardware called "firmware". The user does not know that the function is in the firmware because the computer accepts and executes the instructions either through stored logic in the ROM or directly through hardware.

More and more firmware is appearing in the newer systems – a trend that is likely to continue. This approach permits a computer with stored logic capabilities to be microprogrammed to accept instructions for any other computer without a substantial cost or hardware modification. Also firmware provides a simple means for adding new functions to the equipment, whereas changing the hardware functions can be costly and at times impossible. Attempting to use software may be too slow and cumbersome.

What is Microprogramming? In the 1950s, M.V. Wilkes introduced microprogramming as a systematic alternative for designing the control section of the computer. Other equally important factors are: $-\operatorname{Microprogramming}$ offers an economical approach that grants large instruction sets to the computer systems.

- Maintenance and diagnostic aids can be incorporated, thus providing excellent diagnostic information for the service engineers.

-Emulation of different machines is easily achieved. -Microprogramming renders a flexible design that allows easy system updating.

Consequently, microprogramming suggests an orderly technique for designing and organizing the control signals that represent the computer states and the orderly transition between these finite states. This can be considered as a direct replacement for the sequential logic control circuits of the second-generation machine.

A suitable definition (suggested by Samir S. Husson) that sums up microprogramming is:

A technique for designing and implementing the control function of a data processing system as a sequence of control signals to interpret fixed or dynamically changeable data processing functions. These control signals, organized on a word basis and stored in a fixed or dynamically changeable control memory, represent (Continued)

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software to hardware (Cont'd)

....

the states of the signals that control the information flow between the executing functions and the orderly transition between these two signal states.

Why Microprogramming? In a microprogrammed system, small routines, stored in either a ROM, semipermanent RMM (read-mostly memory) or RAM (random-access memory), specify the actions and the information flow within the computer. At first, the original concept did not excite computer manufacturers because reliable, inexpensive and fast ROMs were not available. Today, the microprogrammed processor enjoys a high degree of popularity attributed to its inherent flexibility and economic superiority over the designs of conventional computer systems.

Basicially, three computer generations exist. They are defined as:

1st Generation – instruction sets were not stored in the memory of the computer.

2nd Generation—instructions and data could be stored in the computer memory.

3rd Generation—basic instruction set and data flow are controlled by a microprogram stored in a separate control storage unit. Generally, a third generation computer can emulate any other computer because of its architectural constraints as defined by the microprogram.

With microprogramming, one control word performs many functions. Even with a variety of machine instructions as control words, essentially any control or arithmetic function can be generated. Since the basic machine is under microprogram control, multiple precision algorithms can be used to generate either a byte, word, or double-word oriented machine as seen from the outside world.

When using microprogram for diagnostic checkouts of the hardware, all basic phases of the machine design are evaluated and a printout is provided for the user upon request. These diagnostics can be such that they obtain timing from the central processing unit (CPU) only when the CPU is in a quiescent condition. With concurrently running programs, the diagnostic occurs only when time is available. Therefore, the CPU performance is not degraded with respect to the running program(s).

Software to Hardware. To understand how a processor can be microprogrammed (see "Generation Gap") assume the following structure for a hypothetical 60-bit control word:



Assume the following instruction:

Transfer main storage word, as addressed by registers SA1, SA2 and SA3 to the A bus. Contents of the GP register are placed upon the B bus. Add contents of A and B busses. Place results into local storage address 45. No skew is rendered to the D bus. No constant is emitted from the control word to the B bus. Branch 4 ways depending upon whether the memory is ready and ST3 = 1. Reset status register bit 5. Designate control word to compute mode. Most-significant-bits of next address are 63.

To perform this operation, a typical microinstruction mnemonic form could be written as follows:

 $MS + GP \rightarrow LSAR$ (combine main storage word (MS) and GP register content and place results into local storage address (LSAR))

CSK = 0 (no skew is rendered to the D bus)

CK = 0 (no constant is emitted from control word to B bus)

CH = Mem Red? (Memory ready?)

CL = ST3 = 1? (check register SA3 contents)

CS = 12 (reset status register ST5)

CM = 0 (compute mode)

CN = (most-significant-bit of next control word address)

CP = control word parity.

- CA = 0000100101 = main storage address MS
- CB = 10 = GP register content
- CC = 0000 = add command
- CD = 0000101101 = local address 45

CSK = 000 = no skew or no shift required

- CK = 00000000 = no constant
- CH = 0110 = memory ready command
- CL = 1101 = check ST3 = 1
- CS = 1100 = 12 for resetting register ST5
- CM = 00 = compute mode
- CN = 0110 = 6 the most-significant-bit of 63
- CP = 100111 = parity for control storage.

Several microinstructions, such as the 60-bit control word previously described, make up a microprogram. A typical microprogramming effort begins with a program flow chart and proceeds in the following sequence to the insertion into a ROM.



STEP 1. Programmer generates a two-dimensional representation of the problem-solving procedure – the flowchart.

IK. CP	ст	0	CT2	OPE 12	OP4 12	DD	
JK+Gr	51,	0	515,	UF5=11	UF4=1	BR	
L+NoP	JK,	0	ST4,	ST3=1?	ST2=1?	BR	
L●GP	W,	0	ST1,	ST4=1?	OPS=1?	BR	
TU•GP	RS,	N	OP,	NOP,	OP4=1?	BR	
TU SLPS	GP,	0	STS,	ST7=1,	ST6=1	BR	

MNEMONIC ENCODING OF MICROPROGRAM

STEP 2. Using the flowchart, the programmer mnemonically encodes the microprogram onto a standard coding sheet.



STEP 3. Information on the coding sheets is transferred onto standard IBM cards. These cards are then fed into a computer containing a special compiler and logical description of the final system hardware.

ADDRES	S WORD
203	01100111010101
204	11100110110110
205	0000111010101
206	10001101100111
207	01010111111000
208	11101011010110
209	11001100010000
210	110111111001010
211	011101101011110
BINA	Y MICROPROGRAM

STEP 4. After the program is compiled and translated, the resultant binary truth table is dumped onto a printout or tab run and the computer memory retains a copy. A special subroutine then interrogates the truth table stored in memory and transfers the encoded microprogram onto magnetic or paper tape.



STEP 5. The tape then controls a special numerical control machine (such as a weaving machine) that is capable of entering the desired microprogram into some type of ROM system.



STEP 6. The final ROM is tested and inserted into the operating system.

What is the Price? For elementary computing systems, sequential control logic appears to be the easiest design approach. For example, presettable and ring counters can provide all of the necessary control for many systems. In addition, microprogramming techniques may be impractical because of the cost associated with address sequencing and memory selection circuitry regardless of how simple the system is.

There is a great deal of dissension about when it becomes necessary to transcend from sequential logic to microprogramming techniques. Based on past studies, it appears that when the number of sequencing cycles exceed 256, microprogramming is the best approach. When the number exceeds 512, microprogramming is definitely the way to go.

The first large-scale computer to embody microprogramming was the IBM 360. Soon to follow were the System/370 and the RCA Spectra, both based on almost identical machine language. In fact, the similarity is so close that for all practical purposes, the two machines (Continued)

(B) TYPICAL CPU ARCHITECTURE





GENERATION GAP

Basic building blocks for any computer are Input, Output, Control, Arithmetic/Logical Unit (ALU) and Memory. Block diagram (A) represents both second- and third-generation processors—difference is in the control unit. The secondgeneration machine uses sequential logic and the third is based on microprogramming.

Diagram (**B**), a third-generation computer, illustrates the methods of interfacing main storage, local storage and I/O devices via standard channels and a method for handling interrupts. Basic data flow through ALU is from the A and B busses to the D (destination bus). Encoded control storage for ALU field specifies the arithmetic or logic function to be performed. Control storage for CA and CB fields specifies the contents of one register to be entered on the A and B busses.

Control storage for CD field selects the register that is to receive the D bus content. A mathematical expression for this operation is $A \otimes B \rightarrow D$ (B operates on A according to function \otimes and results are transferred to D). Typical ALU functions include:

Instruction	Binary Code
0. Add Binary	0000
1. Subtract Binary	0001
2. Multiply Binary	0010
3. Divide Binary	0011
4. Shift Left	0100
5. Shift Right	0101
6 Logical AND	0110
7. Logical OR	0111
8. Exclusive OR	1000
9. Logical NAND	1001
10. Logical NOR	1010
11. Exclusive NOR	1011
12. Add Decimal	1100
13. Subtract Decimal	1101
14. Multiply Decimal	1110
15. Divide Decimal	1111

It can be seen that an ALU function can process the contents of any register and transfer the results to any register.

A status register provides flexible branching conditions. This simplifies the generation of standard microsubroutines that can be shared by a variety of microroutines and permits programming redundancies to be removed.

Three discrete registers address the main storage. The word to be accessed or written is processed via MS REG-ISTER.

Input/output is accomplished through a standard I/O channel – basically four registers:

Input Data Register

Input Tag Line Register

Output Data Register

Output Tag Line Register.

Several identical channels can exist and are selected by the CHS REGISTER. This approach for channel I/O allows IBMcompatible multiplexer, selector and BLOCK multiplexer channels to be programmed. This type of architecture could be microprogrammed for an entire IBM 370 instruction set, including microprogrammed supervisory capability.



MICROINSTRUCTION DATA FLOW

Typical data flow for a microprogrammed minicomputer is depicted above. The computer is comprised of input registers "L" and "M", output registers "W" and "X" and memory or storage registers GP, OP, ST, PO, JK, RS, TU and V. Contents of any register connected to the "A" bus are transferred to the A register via the A bus under control of the ROM. This also applies to the B bus and register. Encoded ALU function, provided by the control storage, combines the contents of the A and B register. ALU output is transposed to the D bus and gated to the register specified by the control storage. Branch circuits determine the microinstruction to be executed.

To illustrate an operation, the data flow for an assumed instruction $JK + GP \rightarrow ST$ is indicated in color. Binary word and its derivation are shown below:

Mnemonic:	JK	+	GP	\rightarrow ST
Numeric:	4	7	0	2
Binary:	0100	111	0000	0010
Microinstruc	tion: 0100	0111000	000010	

Portion of the control storage associated with branching is not indicated.

(Continued)

software to hardware (Cont'd)

can be considered compatible—a very important feature so that one microprogrammed processor can emulate another. The following list tabulates the advantages of the third-generation computer architecture compared to the nonmicroprogrammed machines.

EMULATION – Ability of one computer, when properly microprogrammed, to perform a task that is fully compatible with another.

STANDARD ARCHITECTURE – All third-generation computer architectures are similar.

DIAGNOSTICS-It is possible to have diagnostic routines as part of the resident microprogram.

GENERAL CHARACTERISTICS – Truly general purpose is the nature of the third-generation machines, thus they can be microprogrammed as central processors or peripheral controllers.

FIELD MODIFICATIONS—Core ROMs permit easy word alterations in the field.

EXPANDING PERFORMANCE ECONOMY – Addition of new features to a system can be simple.

Fourth-generation computers have not been previously mentioned because they operate with thirdgeneration hardware. Basically, fourth-generation machines possess more sophisticated microprogramming to attain features such as virtual systems, virtual

Plug-to-plug ROMs and RAMs provide control storage for third-generation computers. Writable control storage is preferred for prototype work; read only is much more cost effective and is preferred in production systems. The table compares these two types of storage. memory and paging. In general, one might conclude that for medium to large systems, dedicated or not, a third-generation or a microprogrammed technique appears to be the best approach.



Coauthors of this article are **J. Kjell Hovik** and **Winston W. Hodge** of Datapac, Inc., Costa Mesa, Calif. Mr. Hovik, president, received his B.S.E.E. and M.S.E.E. from the Norwegian Institute of Technology. His past experience includes the position of manager of memory development at Varian Data Machines. Mr. Hodge, director, Systems Architecture, holds three patents. He received his B.S.E.E. from Chapman College and is presently doing graduate work at UCLA and California State College.



dipole concept improves readback analysis

Effects of the gap variation between the read head and the surface of a magnetic memory drum can be unpredictable. Using a magnetic dipole concept, a designer attains a better understanding of the readback process without degradation to the accuracy of his design prediction.

An exact analysis of magnetic circuits usually leads to complicated calculations. For engineering purposes, however, selecting the appropriate mathematical model permits the derivation of a relationship that can be effectively applied to design predictions. One of these idealizations is the "magnetic dipole." Employing this concept, an order-of-magnitude value for the amplitude of the readback signals from a magnetic memory drum can be defined.

Basically, a memory drum is a rotating cylinder driven by a synchronous motor. The recording medium is a magnetic material, such as red iron oxide (Fe_2O_3), that is generally placed in a series of grooves parallel to the drum rotational axis.

On the drum periphery, a set of recording heads is mounted. These heads write or read information from the drum surface either by magnetizing small areas or by sensing the magnetization of areas where information has been previously recorded. For this discussion, it will be assumed that the medium directly under the head is in saturation. Strength of the magnetization depends upon the retentivity of the medium, and the write-head current establishes the direction that determines the recorded information. Thus, each bit of information on the drum surface is essentially a small piece of magnetic material as shown in **Fig. 1**. These bits are assumed to be sufficiently spaced not to interact with each other.

For calculating the magnetic flux density distribution in the vicinity of the magnetized oxide, an equivalent magnetic dipole of length "L" will represent a bit. However, since the transversal dimensions "l" and "h" of the equivalent magnet in **Fig. 1** are not negligible when compared to "L", the magnetic flux density amplitude should be corrected to account for the physical shape of the real oxide bit. By comparing the flux densities created by the ideal magnetic dipole discussed in **Fig. 2** and the physical magnet in **Fig. 1**, the required correction factor can be determined as illustrated in **Fig. 3**.

Putting the Theory to Work To demonstrate how to use the magnetic bipole concept, assume a drum system with the following parameters:

On the drum surface, a small magnet with the following dimensions represents each bit of information: L = 0.0045 inch, l = 0.050 inch and h = 0.0015 inch. Fig. 1-Each data bit on the memory drum surface consists of a small piece of magnetic material. Depth of the magnetic medium is "h", the write head defines the transversal dimension "l" and "L" is the length of an equivalent magnetic dipole for each bit.



1111

Retentivity of the recording medium is $B_1 = 450 \times 10^{-4}$ Wb/m². From Eq. (2-4), the magnetic moment is $M = 4.16 \times 10^{-8}$ A × m². Applying Eqs. (2-5) and (3-9) to OP = x = L = 0.0045 inch yields the correction factor k. Eq. (2-5) defines the magnetic flux density induced in P by the magnetic dipole or B = 12.7 × 10⁻⁴ Wb/m². For the case of the real magnet, Eq. (3-9) determines B in P or B = 2.55 × 10⁻⁴ Wb/m². The ratio of the two calculated flux densities represents the correction factor or k = 5.

The magnetic flux density component normal to the drum surface is evaluated for specific positions using Eq. (3-10). To illustrate, the results for two consecutive bits magnetized in the same direction are tabulated and plotted in Fig. 4.

Readback Voltage Calculation For evaluating the readback signal amplitude, some additional parameters will be defined and introduced where needed in the calculation. In **Fig. 5**, the assumed read-head-drum gap is H = 0.001 inch. If the read-head pole area is A, the expression for the magnetic flux in the head is:

$$\phi = \mathbf{A} |\overrightarrow{\mathbf{B}}_n| \mathbf{W}\mathbf{b}$$

Applying Lenz's Law, the voltage induced in the head is: $\overrightarrow{}$

$$\mathbf{V} = rac{\Delta \phi}{\Delta \mathbf{t}} = rac{\mathbf{AN} \ \Delta \ |\mathbf{B}_N|}{\Delta \mathbf{t}}$$

where N is the number of turns of the read-head winding.

Referring to **Fig. 4** and using linear approximation, the magnetic flux density varies from circa 0 to 3.84×10^{-3} Wb/m² between points A and B, and from 3.84×10^{-3} to 0 Wb/m² between points B and C.

$$\Delta |\dot{B}_{v}| = 3.84 \times 10^{-3} \text{ Wb/m}^{-3}$$

If Δt_1 and Δt_2 represent the time required for the read head to travel from points A to B and B to C, respectively, then

$$\mathbf{V}_{pk\text{-}pk} = \mathbf{AN} \left(\Delta |\vec{\mathbf{B}}_{N}| \right) \left(\frac{1}{\Delta \mathbf{t}_{1}} + \frac{1}{\Delta \mathbf{t}_{2}} \right)$$
(Continued)

....

dipole concept (Cont'd)





Fig. 2–Magnetic moment $\vec{qL} = \vec{M}$ characterizes equivalent magnetic dipole of length "L" where "q" is pole strength. Magnetic flux density in "P" located at "r" distance from the dipole center "O" is \vec{B} .

Components \vec{B}_r and \vec{B}_r make up \vec{B} and are defined as:

$$|\vec{B}_{r}| = \frac{\mu o}{2\pi} \frac{M}{r^{3}} \cos \sigma$$
(2-1)

$$|\vec{\mathsf{B}}_{r}| = \frac{\mu \sigma}{4\pi} \frac{\mathsf{M}}{\mathsf{r}^{3}} \sin \sigma$$
 (2-2)

where $\mu o = 4\pi \times 10^{-7}$ is the permeability of free space.

Magnetic oxide compound specifications usually provide retentivity B, (Wb/m^2) of the coating following saturation. Applying **Eq. (2-1)** at the positive tip of the magnetic dipole yields:

$$|\vec{\mathsf{B}}_r| = \frac{\mu o}{2\pi} \frac{\mathsf{M}}{\left(\frac{\mathsf{L}}{2}\right)^3} = \mathsf{B}_r$$
(2-3)

and
$$M = \frac{B_I}{\mu_0} \times \frac{\pi L^3}{4}$$
 (2-4)

Combining Eqs. (2-1), (2-2) and (2-4) yields:

$$\vec{|B}_r| = \frac{B_r L^3}{8 r^3} \cos \sigma$$
 (2-5)

$$\vec{|B_t|} = \frac{B_t L^3}{16 r^3} \sin \sigma$$
 (2-6)

Components $|\vec{B}_r|$ and $|\vec{B}_t|$ can be expressed in terms of H– distance between point P and the drum surface: H = r sin σ (2-7)

$$H = r \sin \sigma$$
 (2-7)
Then **Eqs. (2-5)**, (2-6) and (2-7) give:

$$\vec{|B}_{r}| = \frac{B_{l}L^{3}}{8\frac{H^{3}}{\sin^{3}\sigma}} \cos \sigma = \frac{B_{l}}{8} \left(\frac{L}{H}\right)^{3} \sin^{3}\sigma \cos \sigma$$
(2-8)

$$\vec{|B}_t| = \frac{B_t L^3}{16 \frac{H^3}{\sin^3 \sigma}} \sin \sigma = \frac{B_t}{16} \left(\frac{L}{H}\right)^3 \sin^4 \sigma$$
(2-9)

Modulus of \vec{B} at point P is:

$$\vec{|B|} = \sqrt{\vec{|B_t|^2 + |B_r|^2}}$$

$$\vec{|B|} = \frac{B_I}{8} \left(\frac{L}{H}\right)^3 \sin^3 \sigma \sqrt{\cos^2 \sigma + \frac{\sin^2 \sigma}{4}}.$$
 (2-10)

Another component of \vec{B} used in evaluating readback signal is the projection \vec{B}_{N} of \vec{B} on the normal to the drum surface:

$$|\vec{\mathsf{B}}_{N}| = |\vec{\mathsf{B}}| \cos\left[\frac{\pi}{2} - (\sigma + \alpha)\right]$$
 (2-11)

Drum diam = 4.5 inches Drum speed = 100 rps

$$\Delta {
m t}_1 = rac{0.0043}{\pi imes 4.5 imes 100 imes 2} {
m sec} \ \Delta {
m t}_2 = rac{0.0045}{\pi imes 4.5 imes 100 imes 2} {
m sec}$$



Fig. 3–Magnet transversal dimensions affect the magnetic flux density created at any point in the proximity of the oxide bit. A correction factor k compares the magnetic flux densities induced by the real magnet (Fig. 1) and the equivalent dipole (Fig. 2). Since the ideal magnetic dipole and the oxide bit were assumed to be equivalent for calculating Eq. (2-11) in Fig. 2, their magnetic moments M are equal. With reference to the diagram, the small area dS on the magnet's positive end bears a magnetic charge I dS where I is the magnetization constant defined by

$$I = \frac{M}{V}$$
(3-1)

and where V = (h) (1) (L) or the equivalent magnet volume. Coulomb's Law gives the magnetic flux density created at point P by I dS:

$$dB = \frac{\mu o}{4\pi} \frac{I \, dS}{r^2} \tag{3-2}$$

Resultant of two symmetrical elements dS is along axis O-x. Thus:

$$dB_1 = dB \cos \sigma = \frac{\mu o}{4\pi} \frac{1 \, dS \cos \theta}{r^2}$$
(3-3)

Or because dS = h dl,

$$dB_1 = \frac{\mu_0}{4\pi} \frac{l h dl}{r^2} \cos \theta$$
(3-4)

Eq. (3-4) can be rewritten in function of OP =
$$x = r \cos \theta$$
:

$$dB_1 = \frac{\mu o}{4\pi} \frac{I \ h dI}{x^2} \cos^3 \theta$$
(3-5)

Finally, because tan $\theta = \frac{1}{2}$

$$\frac{d\theta}{\cos^2 \theta} = \frac{dI}{x} \quad \text{Or} \quad dI = \frac{x}{\cos^2 \theta} d\theta$$

Eq. (3-5) becomes:
$$dB_1 = \frac{\mu o}{t} \frac{lh}{t} \cos \theta d\theta \qquad (3-6)$$

 $dB_{1} = \frac{\mu\sigma}{4\pi} \frac{m}{x} \cos \theta \, d\theta \qquad (3-6)$ Integration of **Eq. (3-6)** over the entire positive face of the magnet yields:

$$B_{1} = \frac{\mu o \ln}{4\pi x} \int_{-\theta_{1}}^{+\theta_{1}} \cos \theta \, d\theta = \frac{\mu o \ln}{2\pi x} \sin \theta_{1}$$
 (3-7)

Using similar calculations, the contribution of the magnet negative face to the flux density at point P is:

$$B_2 = \frac{\mu o \ln}{2\pi (x + L)} \sin \theta_2$$
 (3-8)

Therefore, the total flux density at point P equals:

$$B = B_1 - B_2 = \frac{\mu o \ln}{2\pi} \left(\frac{\sin \theta_1}{x} - \frac{\sin \theta_2}{x + L} \right)$$
(3-9)

Correction factor k is the ratio of the two flux density values at point P. Ratio between **Eqs. (2-5)** and **(3-9)** serves as the correction factor for the flux density amplitude given by **Eq. (2-11)**. Therefore, the flux density distribution around the magnetized bit is:

$$\vec{|B}_{N}| = \frac{1}{k} \vec{|B}| \cos\left[\frac{\pi}{2} - (\sigma + \alpha)\right]$$
(3-10)

Therefore, the readback voltage pk-pk is:

DRUM SURFACE

$$\begin{split} \mathbf{V}_{pk\text{-}pk} &= \frac{4.8 \times 10^{-4} \times 600 \times 3.84 \times 10^{-3}}{1550} \\ & \left[\frac{2\pi \times 4.5 \times 100}{0.0043} + \frac{2\pi \times 4.5 \times 100}{0.0045} \right] \\ \mathbf{V}_{pk\text{-}pk} &= 0.9 \mathbf{V} \end{split}$$

Empirical Results and Conclusions This analysis was successfully used to estimate the effect of the read-headdrum gap variation on the readback amplitude. Actual measurements made on related hardware indicated maximum readback signals of 800 to 900 mV, averaging generally 600 to 700 mV. The fact that the calculated readback signal is on the high side, compared to the empirical results, is because of the idealized models used in the analysis. When combined with

L'/2

ANGLE o

90

12

240

90

TABLE I

BN

0.086

0.296

3.84

0

POSITION

2

3

4

OXIDE

Wb/m²

10-3

10-3

10-3

experimental measurements, the equations discussed provide a better understanding of the magnetic drum readback process without too greatly reducing the accuracy of the design predictions.



Charles Benet is a senior engineer with Singer/Kearfott Div., where he has project responsibility for the Centaur guidance computer. In France, Charles received an Engineering Diploma from the Institut Superieur d'Electronique du Nord and an M.S. in Physics from Lille University. He has held various engineering positions in France, Switzerland and the United States.







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ROM/RAM merger forms a strong team

An electrically alterable ROM is an ideal means for storing microprograms. A semiconductor concept combines a RAM with a reprogrammable ROM.

Because biax and plated-wire memories are essentially electrically alterable read-only memories (ROMs), they have been an obvious choice for a microprogrammed system in the past few years. Cost and availability of these systems, however, have been generally unsatisfactory for the gain in system performance. In the search for a low-cost microprogrammed system with high reliability, braided wire ROMs, diode matrices and resistor matrices have also been considered.

More recently semiconductor ROMs have been well received because of size, cost and power requirements and improved performance. But access time is important. In many cases, the 500- to 1000-nsec MOS devices are too slow. Bipolar, on the other hand, is expensive, but offers the necessary access time. Both MOS and bipolar ROMs lack ease of alterability, however-once an element is programmed it is permanent.

Now, solid-state reprogrammable ROMs are available with access times of 700 nsec – again too slow for most applications. However, the combination of a high-speed RAM with a reprogrammable ROM offers an excellent vehicle for those in need of a high-speed microprogram store. Such a system is easily changed either by changing the system, changing the plug-in MOS elements or by reprogramming the elements and replacing them in the system.

The block diagram illustrates a system that contains a reprogrammable ROM, a bipolar RAM and a control section. When the system is turned ON, the contents of the ROM are transferred to the RAM. The unit then provides output data on a 75-nsec access time basis from a stable address input.

This system is especially useful for debugging microprograms requiring bipolar speeds and applications needing frequent program changes of the ROM. Because the ROM is reprogrammable, the cost of a program change is only the time required to erase and reload new information.

Hugh DeVries, one of the founders and vice president of engineering of Monolithic Systems Corp., Denver, Colo., previously was chief engineer for the Denver Systems Div. of Ferroxcube where he directed memory and computer system design. DeVries received his B.S.E.E. from the University of Nebraska. He has two patents pending and is a member of IEEE.





System block diagram illustrates the signal flow between the reprogrammable ROM, the bipolar RAM and the control circuitry. Control section consists of multiplexing and timing circuits, up/down counters, an oscillator (clock) and a turn-on timer. When the system is turned ON, the ROM contents, under control of the oscillator and counters, are transferred to a location in the RAM, indicated by *Memory Address*. Timer permits external addressing of the bipolar RAM, thus providing high-speed access.

A microprogram instruction may require several ROM

words because of bit lengths. For example, if the ROM words are only 8 bits in length, 12 ROM words will be transferred into the RAM for a 96-bit instruction. The unit then provides the output data on a 75-nsec access time basis from a stable address input.

A workable system was developed that is TTL compatible and requires 5 and -12V dc. Word sizes were 256, 512, 1k and 2k with bit lengths up to 96 bits (256-word system). The system is packaged on a 9.75by 15- by 0.4-inch PC board that has two 70-pin edge connectors on the 9.75-inch side.

events

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1971 IEEE INTERNATIONAL COMPUTER SO-CIETY CONFERENCE, Sept. 22-24, Boston, Mass. All topics relate to the development and the use of quantitative methods for designing and evaluating computer systems. The presentations will focus on the computer component, be it hardware, software, firmware or a combination.

Conference keynote speaker is Edgar D. Mitchell, Apollo 14 Lunar Module pilot, and the luncheon guest speaker is Robert C. Townsendauthor of Up the Organization. Registration fees that cover the technical sessions (total of 26) and a copy of the conference proceedings are: \$35 (advance) and \$45 (at conference) for members: \$45 (advance) and \$55 (at conference) for nonmembers; free for IEEE students and \$2 for non-IEEE students (sessions only). Students must purchase the proceedings and luncheon tickets separately. For advance registration, contact: 1971 IEEE Computer Conference, General Delivery, Kendall Square Post Office, Cambridge, MA 02142.

INPUT/OUTPUT SYSTEMS SEMINAR 1971, Oct. 12-14, Chicago, Ill. This 3-day seminar is dedicated to the total systems concept and will include presentations by major manufacturers of input/output equipment.

Presentations on Oct. 12 will include card oriented peripheral equipment and output EDP printers, both impact and nonimpact. The second day will be devoted to plastic card terminal equipment with applications in such fields as banking, health/welfare, industrial, retail and others, plus memory products including perforated tape and key-input data entry.

OCR/OMR equipment and applications will be covered on the final day. Two evening sessions will deal with plastic card security and EDP supplies.

For further information contact:

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events

C. A. Greathouse, Data Processing Supplies Association, Box 1333, Stamford, CT 06904.

AUERBACH DATA COMMUNICATIONS CON-FERENCE, Oct. 5-6, New York, N.Y. The 2-day program will provide executives with information on planning and fianancing a data communications system, emphasizing the use of information as an operational and management resource. Registration fee for all events and work material is \$300. Advance registration for one or more individuals may be made on company letterhead, accompanied by a check made out to Auerbach Data Communications Conference or with approval to bill the registrant's company. For further information and advance registration, contact: Auerbach Data Communications Conference, 9th Floor, 300 Madison Ave., New York, N.Y. 10017. Telephone: (212) 986-1270.

coming courses...

COMMUNICATIONS TECHNIQUES FOR TELE-PROCESSING, Oct. 10-13, St. Charles, Ill. Participants will become acquainted with the fundamental concepts and constraints of communication techniques for teleprocessing. They will learn telecommunications fundamentals, become exposed to today's communication techniques and evaluate current services, systems and products. Topics to be discussed include communication network concepts and economics, modulation concepts and modems, time-shared and batch terminal characteristics, error detection and protection, multiplexing, message switching and data concentration. The latest terminal equipment will be demonstrated, including alphanumerical CRT, graphics and facsimile. For 10 sessions, the cost is \$390. For further information, contact: National Electronics Conference, Inc., Oakbrook Executive Plaza, Suite 629, 1211 W. 22nd St., Oak Brook, IL 60521.

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01105

Progress in Products

LSI and LEDs Produce Truly Portable Digital Multimeter

PROGRESS IN INSTRUMENTATION

Seventeen ranges at 3-1/2-digit resolution are delivered by a little 2-1/4-lb multimeter being introduced by Weston. The Weston 4440 joins the Honeywell 500 multimeter (imported from France) in giving engineers and technicians nearly benchtype accuracy and measuring versatility in a package that can be carried anywhere. The cost of the Weston 4440 is in the same \$300 range as the Honeywell 500 (both with batteries). However, the Weston "minimultimeter" carries its batteries as an integral part of itself and has automatic polarity switching.

The 4440 is a timely addition to the Weston 1240 family of semiportable, bench-type digital multimeters. One 24pin MOS LSI DIP in the 4440 (made by a well-known MOS vendor) replaces 18 bipolar DIPs (some MSI) used in the 1240. One little plug-in card mounts 3-1/2 digits worth of Monsanto LED segments in the 4440, replacing the 3-1/2 "Nixie" tubes used in the 1240. Both these advances help the 4440 save PC board space and power. They are part of the reason that the 4440 can run 8 to 12 hours continuously off four C cells, while the 1240, like some other bench instruments, can only run approximately 6 hours off much larger and more expensive add-on battery packs. (The 1240 pack uses 12V Globe "gel/cells.") However, the 4440 does not have quite all the ranges of the 1240, nor does its 0.3% accuracy quite match the 0.1% of the 1240.

LSI-Controlled Dual Slope

The 4440 uses the same continuously self-adjusting type of dual-slope analog-todigital conversion as the 1240. Rotary and pushbutton switches on the front panel (see photos) connect the two leads directly to the A/D converter in the instrument's basic dc mode (going by way of an attenuator on the higher ranges, of course). The A/D converter consists of a "free-running" IC op amp integrator with a 2- μ F polyester feedback capacitor. It charges up and



Less than \$300 buys this little multimeter which can read ac and dc voltages and currents and measure ohms, all with 3-1/2-digit resolution. It is a beautiful example of how various aspects of modern technology – MOS LSI, GaAs LEDs, high-performance IC op amps, PC-mountable switches, injection-molded cases – can work together to produce considerable "progress." These photos are of the prototype; production version will have a battery-test position on the front panel rotary switch and won't have transistor sockets and the PC boards.

down under control of the logic on the LSI chip, counting out the digital result in the process.

The dc voltage being measured is transformed into the current that charges the $2-\mu$ F feedback capacitor by the op amp's input resistor, after the usual manner of operational integrators. Charging continues until a four-decade master timing counter on the LSI chip reaches 9999 and overflows, going to 0000. This happens five times a second because of the fixed frequency of a driving clock on the LSI chip. Then the chip logic causes the correct polarity of the reference current to be applied to the op amp integrator to "overpower" the dc input being measured. The capacitor now discharges.

During the discharge, the master timing counter on the chip is counting up from zero, also performing the function of a measuring counter. A high-gain threshold-sensing amplifier detects when the $2-\mu F$ capacitor has been discharged and causes the master timer's count to be copied into a buffer register. It is this buffer register's contents that are displayed without visible blinking on the LED readout. Obviously, the higher the dc voltages being converted, the longer it will take the given reference current to counteract the input and discharge the $2-\mu F$ capacitor, and the higher will be the count displayed by the LEDs.

To complete the cycle, the threshold amplifier also causes the reference current to be turned off. Then the dc input, acting alone, starts to recharge the $2-\mu$ F capacitor. But the four-decade master timing counter has not stopped. When it again reaches 9999 and goes to 0000, it again turns on the reference and the cycle repeats.

This version of the now universally-popular dual-slope A/D converter (Weston owns the patents and charges others about 3% of sales for their use) is well suited to battery-operated instruments. The clock frequency can drift without affecting the accuracy as long as it does so slowly, for it is just the short-term ratio of the periods that is being measured. But this version does take three or four cycles to settle down to an accurate reading after a large step change of the input.

If the measured voltage is too large for the manually-set range, the reference current will not be able to discharge the capacitor during the 0000 to 9999 count period of the master timing counter. Logic on the LSI chip automatically detects this, causing the overrange "one" and the proper polarity sign to flash a warning. At the same time, meaningless additional digits are blanked to save power.

The LED segments are driven hard on at 125-Hz strobe rate, both to time share the numeral pattern encoding and to produce short, high-current duty cycles that push the LED diodes towards improved electrical-to-optical conversion. It will be noted from the photo that discrete transistors must be used between the LSI chip and the LED display to provide this highcurrent driving.

A Truly Miniature Power Supply

The ability to operate all this elegant circuitry for over 8 hours on just four Ni-Cad C cells results from very careful power budgeting, according to designer Irwin Munt. "We power the LEDs and the operational rectifier used for conditioning ac inputs and most of the MOS chip right off the 5V from the cells," he said. "We purposely chose ion-implanted MOS processing to be able to run the LSI off this low a voltage."

The integrating op amp and the reference currents, however, do need a precision $\pm 12V$. For this, Munt incorporated a small 100-kHz dc-to-dc converter followed by a zener regulator. The photo shows how small this could be made.

Tooled for Low Labor

"Weston is situated in one of the highest-cost labor markets in the U.S., so our designers have had to become adept at tooling products for low-labor-contact," Jack Stegenga, manager of new products, stated. "But we need to be confident that there is a 10,000-units-per-year market for a product like this before we invest in the tooling."

The tooling in this little product is impressive. It starts with the MOS chip, which is a proprietary design worked out by Weston and the semiconductor vendor. It carries through in the way all the parts are mounted on two PC boards with no hand soldering. It is completed by the sophisticated plastic cases for the instrument and the batteries.

Weston has been a pioneer in using the latest innovations in rugged, injectionmoldable thermoplastics (see EDN/EEE Aug. 15, p. 14). An examination of these parts reveals such clever details as molded-in holes for spare fuses in the battery case and molded-in slides for holding the PC boards in the main instrument housing. They have even molded in additional grooves for future improvements – a thermal print-out being one possibility.

Weston Instrument Corp., 619 Frelinghuysen Ave., Newark, NJ 07114. 359





Miniature Capacitor First With Multilayer Dielectric

PROGRESS IN COMPONENTS

Nearly 14 years of research effort have culminated in the introduction by Industrial Condenser Corporation, Chicago, of the first commercial, multilayer dielectric, miniature metallized capacitors. The new polypropylene molded units, designated Type LALZ "Multifilm" and available in values from 0.2 to 7μ F, feature four individually-applied and polymerized layers of a plastic lacquer dielectric totalling no more than 2.5 microns in thickness.

The capacitors match the physical size of conventional single-film, thin-layer, miniature metallized types with identical rating, and are substantially smaller than metallized "Mylar" units. More significantly, they offer higher reliability than conventional film designs and, surprisingly, cost less to manufacture, resulting in a lower price tag.

For the future, the company reports that even thinner multiple-layer dielectric films are under development, which should permit the production of the smallest plastic-film capacitors ever marketed.

Why a Multilayer Dielectric?

The electronics industry has long desired a multilayer, miniature plastic film capacitor, but until now no one has been to commercially produce such a device whose total dielectric thickness did not surpass the thinnest single-layer cast or extruded films incorporated in conventional designs.

As a leading manufacturer of single-

film, miniature metallized capacitors, Industrial Condenser has long recognized that a multilayer dielectric would inherently offer greater reliability for the simple reason that pinholes or other imperfections would extend only as far through the dielectric as the thickness of one layer, rather than extending through the entire dielectric as in single-film types. The probability of pinholes in four layers lining up is virtually nonexistent. (Paper capacitors always contain multiple layers because of the relatively large number of pinholes in paper compared to plastic film.)

In theory, multilayer miniature capacitors could be produced using several thicknesses of extremely thin, discrete sheets of cast or extruded film similar to that used in conventional capacitors. The problem is that such film is extremely costly and difficult to handle. The lacquer film generation technique has proven to be the more practical answer.

Higher Reliability

The virtual elimination of throughdielectric pinholes and other imperfections in the new "Multifilm" capacitors should substantially reduce the occurrence of catastrophic failures and instantaneous faults and clearings. Freedom from the latter is especially important in applications where circuit energy is insufficient to clear faults or where the circuit disruptions of instantaneous fault/clearing cannot be tolerated.

An ongoing reliability test program recently passed the 1,300,000 capacitor

Performance Characteristics

- Non-polar
- Non-inductive
- Operating Temperature Range: -40 to 85° C
- DC Working Volts: 50vdc
- AC Working Volts: up to 120 Hz 35 V rms (AC Operating Voltage at higher frequencies available on request)
- Surge Volts: 75 V dc
- Test Voltage: 100 V dc 2 sec
- Pulse Circuit Operation available on request
- Insulation Resistance 25° C at rated voltage: 1μF and greater:250 MΩμF minimum Under 1μF: 750 MΩ minimum
- Power Factor 25° C 60 Hz- 0.75% max. 1 kHz - 1.75% max.
- Also available for special applications: 10 Volt Rating - 20,000 Megohm μF 20 Volt Rating - 15,000 Megohm μF
- Std. Cap. Tolerance: Under 1μ F±20% 1μ F and greater ±10%
- Non standard tolerance: available to ±5%
- Leads: tinned copper for PC board soldering
- Enclosure: Molded in high temperature
- polypropylene
 Note: Under development is an additional series of these capacitors having higher insulation resistance.

Use below 5 V dc presently under study - request specific application data if intended use is below this level.

hours mark at 85°C without a single dead short, significant loss of capacitance or change in other characteristics.

Extensive testing is also underway to provide data on instantaneous faults and clearing. To date, these test results indicate that the number of instantaneous faults and clearings is insignificant and considerably lower than that of commonly used metallized film dielectrics.

A further tremendous advantage is that the "Multifilm" plastic is generated, metallized, wound, processed and completed all in one plant, leading to complete control of quality from start to finish, whereas the production of metallized film capacitors in general involves one manufacturer producing the film, another metallizing the film and another producing the capacitor.

Cost Advantage Too

Reliability tells only part of the story. Production economies permit the new "Multifilm" capacitors to be marketed at prices substantially below comparable single-film miniature metallized units and also below the larger metallized "Mylar" components. For instance, a $1-\mu F$ "Multifilm" sells for \$0.23 versus \$0.60 for a comparable thin-layer design and \$0.35 for metallized "Mylar". In the $4-\mu F$ size, a "Multifilm" unit is about \$0.54 versus \$1 for metallized "Mylar"; in the $7-\mu F$ size, about \$0.87 versus \$1.60.

Prospective Applications

Industrial Condenser foresees that its new capacitors will replace aluminum and

New compact 7- μ F "Multifilm" capacitor on left; conventional 7- μ F metallized "Mylar" unit on right.



tantalum electrolytics in many applications, in addition to making substantial inroads into markets typically served by plastic film capacitors. Compared to electrolytics, the "Multifilm" units offer very competitive capacitance-to-size ratios (especially in the smaller sizes), lower costs and more stable characteristics. Additionally, they have unlimited shelf life, offer better high-frequency characteristics and are unaffected by voltage reversals. Industrial Condenser Corp., 3243 N. California Ave., Chicago, IL 60618. **360**



Second-Source Log Amps with a Difference

PROGRESS IN PACKAGED CIRCUITS

Intech has introduced a pair of logarithmic amplifier modules that have the same model numbers as an earlier pair of log amps from Teledyne Philbrick. But, although the new Intech log amps (Models A-4350 and A-4351) are interchangeable with the Philbrick versions in many applications, there are also some important differences.

Size vs Versatility

Intech offers smaller packages and lower costs for its versions, whereas Philbrick offers greater versatility. Thus Intech's A-4350 has package dimensions of 1.5 by 1.5 by 0.5 inch, while Philbrick's 4350 is 2.7 by 2.7 by 0.5 inch. In quantities of 1-9, the Intech modules cost \$85, compared with a price of \$98 for the Philbrick modules. But the Philbrick modules can also be operated in the antilog mode, whereas the Intech versions can only be operated in the log mode.

Philbrick's product manager, Skip Osgood, points out that there would be no advantage in eliminating the antilog function from his company's modules because the same amount of circuitry is needed for both functions—only the interconnections change. Intech, however, used a completely different circuit approach and thus was able to achieve economies by dispensing with antilog capabilities, according to Walter Kaelin, chief engineer. While the internal circuits are different, the pairs of log amps are pin compatible in the logarithmic mode, though Philbrick provides extra terminals for antilog operation.

Positive or Negative

Both companies offer two versions of their log amps—one to provide the log of a positive voltage or current (4350) and the other for use with negative inputs (4351).

Performance of the Philbrick and Intech units is quite similar in most respects. Both versions amplify input currents from 10^{-9} to 10^{-3} A or input voltages from 1 mV to 10V. Both can be strapped to provide slopes of 2/3, 1 or 2V per decade. Both have temperature coefficients of $\pm 0.04\%$ °C over operating temperature ranges of -25 to 85°C. Offset voltage drift (15V/°C) and input offset current (50 pA) are identical for the two pairs.

The two companies differ slightly, however, in the way they specify conformity. Intech specifies accuracy (deviation from best straight line) as $\pm 1\%$ with 1V/decade scaling) over the whole input current range. Philbrick has a similar $\pm 1\%$ conformity spec for the same current range but guarantees a tighter conformity of $\pm 0.5\%$ for the reduced current range of 10^{-8} to 10^{-4} A. Intech engineers also claim that their units have better accuracies in the middle of the current range.

Intech Inc., 1220 Coleman Ave., Santa Clara, CA 95050. **361** Teledyne Philbrick, Allied Dr. at Rte.

128, Dedham, MA 02026. **362**



Intech's compact new log-amp module is only 1.5 by 1.5 by 0.5 inch. A similar unit from Teledyne Philbrick is larger but can also be operated in the antilog mode.

Hewlett-Packard believes that design engineers doing digital IC work should have a scope that's **intended** for digital IC work. You shouldn't have to face a makeshift adaptation of a scope that doesn't really "have what it takes," or an "overkill" unit with lots of capabilities you don't need and can't afford.

That's why we've developed two new additions to the HP 180 Scope System.

The first is a new mainframe, the 180 C/D. Like our 180 A/AR, it's compatible with all 180-System plug-ins to 100 MHz real time, plus the easy-to-use 1 GHz sampling plug-in and the 12.4 GHz sampling/TDR plug-in.

In addition, the 180 C/D incorporates new circuitry advances that allow optimized CRT performance. A 15 kV accelerating potential now gives you greater brightness and higher writing speed. Thus, photographic writing speed is several times faster-1500 div/ μ s (1 cm/div) with the standard P31 phosphor. These advanced capabilities make the 180 C/D fully compatible in single-shot response with the 180 System's fastest plug-ins.

The second bright idea is a new 75-MHz vertical plugin – the 1808A. This bandwidth capability makes the 1808A ideal for testing digital circuits using T^2L or ECL, yet saves you a healthy amount in comparison with a 100– MHz system.

Two bright new ideas I in digital IC testing

As you'd expect, the 1808A gives you the usual selection capabilities found in scopes of this class-deflection sensitivity (5mV/div to 5 V/div) and polarity. In addition, however, the 1808A also gives you a new first-selectable input impedance (50 Ω and 1 M Ω)!

And despite all these advantages, both 180 C/D and the 1808A are priced very competitively. The 180C is under \$1,000; the rack-version 180D is slightly higher. The 1808A is \$880-\$800 without probes. Compatible time bases range from \$450 to \$700.

For further information on either of these new additions to the "more-to-come" HP 180 System, contact your local HP field engineer. Write Hewlett-Packard, Palo Alto, California 94304, for data sheets. In Europe: 1217 Meyrin-Geneva, Switzerland.

> Scopes are changing. Are You?

> > 081/17



CIRCLE NO. 27

Computer Products



Synchro/resolver to digital converter handles either 11.8, 26 or 90V input signals. Conversion accuracy and resolution is ± 1 bit and conversion time is 500 μ sec. Overall dimensions are 5.5 by 4.25 by 1.75 inches. Power requirements are ± 15 V dc $\pm 2\%$ at 100 mA and 5V dc $\pm 2\%$ at 500 mA. Northern Precision Laboratories, Inc., 202 Fairfield Rd., Fairfield, N J 07006. **202**



Strip chart recorder Model 701, is a 4-inch chart width unit with a span ranging from 1 mV to 1V full scale. Other features include 20 ips pen response, $\pm 0.5\%$ accuracy and wide selection of single and dual chart speeds. Combination of floating inputs and zero adjust permit recording of positive or negative signals. Price is \$225. Precision Standards Corp., 1701 Reynolds, Santa Ana, CA 92505. **205**



Optical ROM system, Model 401-22, uses fiber optics rather than the complex and delicate lens systems normally employed, and offers storage capacities of up to 50k bits mounted on an 11- by 13-inch PC board. Standard access time is 150 to 200 nsec. The unit offers rapid and simple field alterability, and can be dot ORed to any desired capacity. Quadri Corp., 2950 W. Fairmont, Phoenix, AZ 85017. **208**



Digital data logger Model 210, features reference junctions, solid-state FET scanning, automatic zero drift correction and a periodic timer for unattended operation. Three function programming allows two thermocouple types and a linear mV range. Basic 10-point system is expandable to 100 points in the same chassis. Exhibiting $\pm 0.01\%$ accuracy, the price is \$2000. Doric Scientific Corp., 7601 Convoy Ct., San Diego, CA 92111. **203**



Digital comparators, Series 270, provide instantaneous warning signals or process control feedbacks whenever preset limits are exceeded. Models are available with front panel limit selection of 3- to 6-digit unipolar or 3- to 5-digit bipolar inputs or remote limit selection of 3- to 6-digit bipolar. Price for the 2.5- by 5.25- by 7.75inch unit starts at \$135. Newport Laboratories, 630 E. Young St., Santa Ana, CA 92705. **206**



Touch-tone terminal T-500 features a 49key alphanumeric keyboard, which includes special characters for data entry via an audio response system. Special circuitry restricts the terminal from sending valid frequencies if more than one key is depressed simultaneously. Unit dimensions are 14.3 by 4 by 10.5 inches, and weight is 5 lb. Price is \$700. Wavetek Data Communications, 9045 Balboa Ave., San Diego, CA 92112. **209**



CIGER, designated "Digicator," is a do-it-yourself item available in either kit form or assembled. Complete schematic and bill of materials are furnished. The unit displays time as hours, minutes and seconds on 7-segment incandescent readouts. Time may be displayed on either 12or 24-hour basis. Cabinet is also available. Discon Corp., 2820 N.E. 4th Ave., Pompano Beach, FL 33064. **204**



Impact printer mechanism DPM-30 is a 30-cps unit that provides all 94 standard USASCII characters including upper and lower case alphabet, numerals, symbols and space. It accepts standard fanfold, sprocket-fed paper in widths from 4 to 15 inches and can handle single or multiple copies – up to four carbons. Unit OEM price is \$750. Typagraph Corp., 7547 Convoy Ct., San Diego, CA 92111. **207**



Desk-top calculator Model 909-01 speaks the universal language of mathematics bypassing the need for computer languages. All keys are programmable, thus reducing programming efforts. As a higher-performance replacement for the Scientist 909, this offers 256 program steps and 26 storage registers. Base price is \$3200. Tektronix, Inc., Box 500, Beaverton, OR 97005. **210**

5 AMP and 10 AMP POWER TRANSISTORS FEATURING: Turn-on Time Less than 10 nanoseconds

Planar Construction

 Typically 500 MH₂, ft

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Solitron's ultra-fast switching SDT 6100 Series is now immediately available at new low prices. These NPN power devices are the fastest switching 5 Amp and 10 Amp transistors in the industry. Order today.

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Type Number TO-5	Type Number TO-60	ВV _{сво}	BV _{ceo}	t ом max.	t off max.
SDT6101	SDT6104	65	30	50 ns	50 ns
SDT6102	SDT6105	65	40	50 ns	50 ns
SDT6103	SDT6106	65	50	50 ns	50 ns

	10 Amp Series			
Type Number TO-5	Type Number TO-60	ВV _{сво}	BV _{ceo}	tом max.
SDT6110	SDT6113	65	30	65 ns
SDT6111	SDT6114	65	40	65 ns
SDT6112	SDT6115	65	50	65 ns



t OFF

max.

65 ns

65 ns

65 ns

TO-5

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CIRCLE NO. 28

55

This new 3½ digit panel meter combines excellent specs., an aesthetic design, quick delivery, compact size and OEM prices of \$95 (Uni Polar) and \$101 (Auto Polar). Check these additional benefits:

- 100% overrange 1999
- 0.1% ±1d accuracy
- Zero bias current
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Send for complete specs. and prices in Bulletin 88.

NOW WE'RE "SMALLEST" ENOUGH TO BE NO. 1

"Smallest" Price \$95 "Smallest" Size 2.6" W. x 3.2" H. x 4.6" D. Computer Products

Plastic card punch, Model 625, converts any properly prepared CR-80 credit/identification card into a dialer card. The machine punches at a rate of 10 cps both data and sprocket holes per Western Electric Specification A-590456 into either embossed or nonembossed cards. Datron Systems, Inc., 100 Route 46, Mountain Lakes, N J 07046. **211**

Memory unit, Model 639, accomplishes input/output signal conditioning, control, scan conversion and storage functions. Using a single-ended scan converter tube, input signals are processed and stored for driving TV displays, printers and other devices. Hughes Display Systems, 2020 Oceanside Blvd., Oceanside, CA 92054.

212

Portable trend recording system C-750 monitors and continuously records the speed of a section or the speed differences between sections of an operating process. Recorder uses a 20-division strip chart 3 inches wide at a standard chart speed of 3 inches/hr (up to 90 inches/hr is available). The Louis Allis Co., Div. of Litton Industries, Dept. P, 427 E. Stewart St., Milwaukee, WI 53201. **213**

Plated-wire add-on memory for the PDP-11 minicomputer, NM-8000 Series, has a total system capability of 64k 16-bit words. The memory is enclosed in a 20- by 12.25by 19-inch cabinet. Systems may be purchased with either 4 or 8k modules and are field expandable. Nemonic Data Systems, Inc., 1301 W. 3rd Ave., Denver, CO 80223. 214

Miniature data recorder combines three proven components. Series 7701 bidirectional totalizer offers up to 7-decade displays including sign. The 13-column highspeed printer, Series 7703, has 16 characters/column and uses standard 3-1/2-inch paper tape. A bidirectional rotary pulse generator, Series 1848, has electro optics capable of producing from 1 to 1200 pulses/ revolution. Veeder-Root, 70 Sargeant St., Hartford, CT 06102. **215**

Two moving-head disc cartridge drives, Models 4047A and 4047B, provide high performance mass storage for NOVA computers. The 4047A contains one removable cartridge $(1.247 \times 10^6 \text{ 16-bit words/car-}$ tridge) and two 2200-bpi moving heads. The 4047B contains both fixed and removable discs and has four 2200-bpi moving heads. Data General Corp., Southboro, MA 01772. **216**

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New flame retardant materials for insulation safety.

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Resin-fiber construction with flame-retardant pressure-sensitive thermosetting adhesive for 130°C use. Excellent conformability. Handles like conventional paper or acetate cloth tapes. Flame-out in 3 seconds or less (ASTM-D1000-70 test). Meets UL flame retardancy requirements for SE-O materials, as well as UL Standard 492.

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For radial and axial lead components thermistors, resistors, RC networks, film foil, ceramic, tantalum, diced chip and mica capacitors. Suited for semi-automatic or automated production equipment. Coats at 300°-350°F. Fast cure time: 2 min. at 350° to 30 min. at 275°F. Meets flame retardancy requirements of UL Standard 492.



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No. 69 — glass cloth, thermosetting silicone adhesive. No. 66 — vinyl, UL recognized 105°C meets MIL-1-7798-A. No. X-1264 — epoxy web solventresistant wire and cable ID tape. "Temflex" Brand No. 2585 — nonadhesive vinyl plastic, flexible, selfextinguishing. "SCOTCHCAST" BRAND RESINS. No. XR-5192 — arc and track-resistant 130°C, liquid epoxy. No. XR-5126 — room-curing two-part epoxy, 130°C, semi-flexible. No. 255 — thermal and mechanical shock-resistant, 130°C, meets MIL-1-16923E.

TUBINGS. "3M" Brand 3001, 3002, 3003, 3008 – extruded vinyl, general purpose, 105°C rated. "Scotchtite" No. 3028 – heat shrink-

Dielectric Materials E Systems Division able, clear or colors, thin wall. UL recognized 105°C, meets MIL-1-631 and MIL-1-23053B.

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Computer Products

Seven-inch reel magnetic tape transport, 7000 Series, has a tape velocity of 18.75 ips and comes in a rack 8.75 inches high. An unusual tape loading feature eliminates the need of a take-up reel, thus simplifing loading and handling operations. Peripheral Equipment Corp., 9600 Irondale Ave., Chatsworth, CA 91311. **217**

Pair of modules, Types 16 and 17, provide signal handling and control logic required for operation of "OMNIGRAPHIC" 3000 strip chart and 4000 T-Y recorders as point plotters. Distances between successive points are 0.025, 0.05, 0.075 and 0.1 inch, selected from the front panel. Houston Instrument, Div. of Bausch & Lomb, Inc., 4950 Terminal Ave., Bellaire, TX 77401. 218

X-Y position indicator, Model 60-228, detects the center of a laser beam at distances up to 30m with an accuracy of ± 4 μ rad (± 0.1 mm at 25m) in each of two axes. Price is \$175. Metrologic Instruments, Inc., 143 Harding Ave., Bellmawr, N J 08030. **219**

Digital logic trainer 2010 permits experiments to be performed in Boolean algebra, counters, registers, arithmetic circuits and other computer functions. Each type of circuit is represented on the front panel using MIL-STD symbols. Price, including software and training manual, is \$395. Digiac Corp., Ames Ct., Plainview, NY 11803. 220

Multiconductor cables for connecting computers and peripheral equipment may be ordered in bulk, cut to length or complete with specified connectors at one or both ends. Also available are cables for connecting CRT terminals with display control units. Anixter Wiring Systems, 325 S. Union St., Aurora, IL 60505. **221**

Option 121 for Series 2000 X-Y plotters, plug compatible with TTY or CRT terminals, permits hard-copy graphic plots. Using the terminal keyboard as an input, the operator inserts the program based on plotter control characters. Printout, identical to the data used for the plot, verifies the operator's program. Valtec Corp., 17751 Sky Park Circle, Irvine, CA 92664. 222 Tightly-sealed cartridge, compatible with IBM 2420/3420 tape drives, reduces tape mounting time to seconds and increases reliability and operating efficiency. Human hands never touch the tape because threading is completely automatic. Memorex Corp., Computer Media, 1200 Memorex Dr., Santa Clara, CA 95052. 223

Optical rotary encoders, MOD-CODER/R, come as complete "do-it-yourself" assembly kits that include incremental encoders with direction sensing and zero indexing, tachometers up to 5000 cycles/rev, rugged all metal construction and plug-in lamp modules with 100,000-hour life. In quantity, price is \$50 each. Sequential Information Systems, Inc., 249 N. Saw Mill River Rd., Elmsford, NY 10523. **224**

Paper-tape readers, Models 5101 and 5401, continuously adjust slewing speed from 300 to 625 cps and/or operate from a 50 to 400 Hz ac input. Controller mounts inside the reader chassis. Chalco Engineering, 15126 S. Broadway, Gardena, CA 90247. 225

Modular data acquisition system, Model 7100, is a general-purpose data logger with a full range of optional accessories to scan, digitize and record up to 100 analog inputs. With an optional acoustical or hardwired coupler, the built-in teleprinter operates as a computer terminal. Monitor Labs, Inc., 10451 Roselle St., San Diego, CA 92121. **226**

Console card reader M 1200 fills the need for an economical high-speed large-capacity punched card reader for standard 80column EIA cards. Reading speed is 1200 cpm and hopper and stacker capacity is approximately 2250 cards. Documation, Inc., 841 E. New Haven Ave., Melbourne, FL 32901. **227**

Microfilm print head for a computer output consists of a 5- or 9-inch precision CRT, deflection driver, high-speed stroke-type character generator and page systems. Configured for OEM usage, the unit has spot sizes from 0.001 to 0.004 inches. Character set and fonts are available per customer request. Kratos Display Div., 7825 Deering Ave., Canoga Park, CA 91304. 228

Speed's the name of the game in the MOS clock driver business these days. Whether you're driving a long shift register or one of the new MOS memories like the MM1103.

That's why the new two-phase MH0026 comes complete with a repetition rate of 5MHz and rise and falls times of 15ns (even while driving a 500pF load). Which makes the monolithic MH0026 as fast as the best hybrids and discrete modules on the market. (Which is even nicer when you consider the long term cost advantages of monolithic over hybrids or discretes.)

The speedy new MH0026 has also been designed to be driven from standard DTL/TTL circuits.

All in all, the MH0026 is a welcome addition to a line of clock drivers which already includes the industry's only TTL compatible clock driver (MH0007), one capable of dc operation (MH0009), a 10MHz clock driver (MH0012), a dual ac coupled driver (MH0013), the world's first monolithic (the low cost MH0025) and a TTL-to-MOS memory interface driver (MH0027).

Incidentally, our drivers are available in TO-5, TO-8 and one watt mini dip packages.

For clock drivers, it would behoove you to write, phone, TWX or cable us today. (Although orders more than a week old will also receive prompt attention.)

National Semiconductor Corporation, 2900 Semiconductor Drive, Santa Clara, California 95051. Phone (408) 732-5000. TWX: (910) 339-9240. Cable: NATSEMICON.



CIRCLE NO. 32

Components



Socket pins are designed for PC board mounting of bi-pin incandescent lamps, indicator lights and LEDs. Component replacement can be done with no additional soldering with the SP-202 pins. Price is \$0.05/pair in quantity. General Illumination, Inc., 2233 University Ave., St. Paul, MN 55114. **229**



Two dc torque motors in a single housing - each driving a separate shaft - provide a compact tape or reel drive unit. Each motor has a peak torque of 1200 oz-in. Model H5500-1000 can be modified to customer requirements. Magnetic Technology, Div of Vernitron Corp., 21001 Kittridge St., Canoga Park, CA 91303. 232



Variable capacitor, Model 7271, features low-loss ceramic dielectrics for fine tuning of crystal oscillators from kHz to GHz frequencies. Range is 0.6 to 4.5 pF with a Q of >2000 at 250 MHz. Price is \$7 to \$1.50 each. Johanson Manufacturing Corp., 400 Rockaway Valley Rd., Boonton, N J 07005. 235



Thumbwheel switches are available in 11, 12 and 16 positions with replaceable code discs. The Type B switch has nine contact springs that wipe across the PCB code disc, and provides up to 9 output lines. Interswitch, 770 Airport Blvd., Burlingame, CA 94010. 230



LED socket assemblies for 8- and 14-lead displays are made of glass-filled nylon with mounting holes and polarization notch. Single units are standard for printed circuit or chassis mounting. Multi patterns are available. Augat Inc., 33 Perry Ave., Attleboro, MA 02703. 233



Cabinet latch installs in seconds with a push-on clip and a positioning set screw. Pawl position is shown by a styled knob that indicates latched or unlatched position at a glance. Southco, Inc., 200 Industrial Highway, Lester, PA 19113. **236**



Subminiature rotary switch with 1/2-inch diam is designed for PC mounting. Models are available in 1, 2, 3 and 4 poles on a single deck with a maximum of ten positions. Prices start at \$2.97 each in 100 lots. Alcoswitch, Div. of Alco Electronic Products, Inc., 8 Marblehead St., North Andover, MA 01845. **231**



Power/clock-pulse distribution bar includes four 13Ω timing-pulse distribution paths, a ground and three voltage distribution lines. Each timing-pulse line is provided with solder eyelets for mounting termination resistors. CAPITRON, Div. of AMP Inc., Elizabethtown, PA 17022. 234



Panel meter features input impedance of 10 M Ω . Optional memory capability holds the last-taken meter reading within an accuracy of 1%. Various meter styles are available, with prices ranging from \$25 to \$30 in 100-unit quantities. Ideal Precision Meter Co., Inc., 214 Franklin St., Brooklyn, NY 11222. **237**



Modular instrumentation amplifiers with rack-mount performance.

With the recent introduction of seven new units, Burr-Brown now offers over twenty modular instrumentation amplifiers, including programmable gain types, that provide a low-cost approach to systems instrumentation. Performance is equivalent to that of rack-mount units — we've simply removed the frills and packed them into compact, rugged, lowcost, modular packages. Of course, if you have to have rack-mounts, remember, we supply those too.

These versatile amplifiers all feature a wide range of gain, set by a single external resistor. Because of their small size, ruggedness, and low-cost, they lend themselves to a variety of instrumentation applications including amplification of signals from transducers — such as strain gage bridges, load cells, thermistor networks, thermocouples, and biological probes. Other applications include: recorder preamplifiers, multiplexer buffers, servo error amplifiers, current sensing, and the measurement of any small differential signal riding on common mode voltages.

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Model Number Input Signal

Output

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C70 4773 001

TRIGAC III C70 4773 013 11.8 V line-to-line 400 Hz 14 bit natural parallel

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CIRCLE NO. 34

Components

Nylon rivets can be easily installed in electrical panel boards with a low-cost hand tool for inserting rivets and driving the center post through the rivet body. Price is \$3.50. Taylor Industries, Inc., Fisher Rd., Howell, MI 48443. 238

Electropneumatic sensor can detect deviations or movements as small as 0.0001 inch with repeatability to 0.00002 inch. Basic sensor module is priced at \$20 in lots of 100. Landis & Gyr, Inc., 4 Westchester Plaza, Elmsford, NY 10523. **239**

Cooler for vertical mounting of plastic power devices will accommodate most single mounting tab and hole-throughcase configurations. For thermal matching, the 6025 will accommodate two devices, one on each side. Prices vary from \$0.14 to \$0.35 depending on quantity and finish. Thermalloy Co., 8717 Diplomacy Row, Dallas, TX 75247. **240**

"Pee Wee Ductor" is a shielded inductor for micro-miniature hybrid circuits that measures approximately 1/8 inch between its leads. Inductance values range from 0.10 to 1000 μ H, ±10%. Nytronics, Inc., Orange St., Darlington, SC 29532. **241**

One-part epoxy coating powder for fast packaging, Novaloy 6521, processes as low as 120°C and coats as fast as 1 sec at higher temperatures. Rogers Corp., Rogers, CT 06263. **242**

Miniature variable autotransformers operate at 50 to 2000 Hz with an output voltage from 0 to line voltage or 10% above. Ratings are 2A for 201 Series and 3A for 291 Series. Staco, Inc., 2240 E. Third St., Dayton, OH 45403. 243

Stepping motor features high torque output and fast response. Designed for use with computer peripheral equipment, the Model SM-024-0035-AA has a step angle of 15° and step accuracy of ± 15 min. maximum non-cumulative error. Price is \$35 in quantities of 1000. Motion Control Systems Div., Warner Electric Brake & Clutch Co., 449 Gardner St., Beloit, WI 53511. **244**

AiResearch electronic cooling systems are built into the F-14.

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Catalog-folder contains complete specifying and ordering data on numeric and caption modules, translator drivers, mounting accessories. Dialight Corporation, 60 Stewart Avenue, Brooklyn, New York 11237. Phone: (212) 497-7600.



Components

Mildly activated liquid rosin flux is nonspattering and low fuming for microelectronic soldering. Microflux No. 5004 exhibits good bonding to passivated surfaces and eliminates the possibility of corrosion after bonding. Alpha Metals, Inc., 56 Water St., Jersey City, N J 07304. **245**

Aluminum magnet-wire conductor called "Hytek-20" possesses high conductivity with improved mechanical properties in the annealed state. It is available in a wide range of magnet wire insulations and sizes. Anaconda Wire and Cable Co., 9501 W. Devon Ave., Des Plaines, IL 60018. **246**

Cermet trimming potentiometers are 3/8inch square single-turn units compatible with wave soldering practices and board washing techniques. Prices of the Series 72 are \$0.70 in 1 to 9 quantities and \$0.49 for 1000 quantities. Helipot Div., Beckman Instruments, Inc., 2500 Harbor Blvd., Fullerton, CA 92634. **247**

Metal hybrid cases are available in 17 standard sizes to accommodate substrate areas of 0.375 by 0.5 inch through 1.125 in². Tekform Products Co., 2780 Coronado St., Anaheim, CA 92806. **248**

PC board mounting kit consists of a 15-pin connector and screw terminals mounted on a small PC board that provides interconnection. Priced at \$10 each, the Model 2005 is ideal for installations where soldering is inconvenient or impractical. California Electronic Mfg. Co., Box 555, Alamo, CA 94507. **249**

Electrically conductive silicone elastomer has a nominal volume resistivity of 1.0 ohm-cm. "SC-Consil" has a temperature range of -75 to 400°F and 65 ± 5 durometer Shore A. Tecknit, 129 Dermody St., Cranford, N J 07016. **250**

Compact optical shaft encoder features solid-state light source. Measuring 1.5 inch in diam by 1.2 inch long, the "Rotaswitch" 860 Series is available with a sine- or square-wave output at various pulse rates and in unidirectional or bidirectional versions. Standard version price is approximately \$125 in single quantity. Disc Instruments, Inc., 2701 S. Halladay St., Santa Ana, CA 92705. **251**

DT-126



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CIRCLE NO. 43

Components

Cadmium-mercury batteries feature long life and operating temperature range from -65 to 200°F. Estimated shelf life at room temperature is 25 years. ESB Inc., 5 Penn Center Plaza, Philadelphia, PA 19103. 252

Edgeboard connector with bifurcated bellows contacts on 0.156-inch centers is designed for use on 1/16-inch circuit boards. Available with single or double readout and 6 to 22 contact positions, the EB7 will adapt to variations in thickness from 0.050 to 0.071 inch. Dale Electronics, Inc., Box 609, Columbus, NE 68601. **253**

Solid-state proximity switch senses metallic material at preset distances from 0.0005 to 0.15 inch. Weighing less than 0.5 oz, the Model 630801 operates from -65 to 250°F. Dynasciences Corp., 9601 Canoga Ave., Chatsworth, CA 91311. **254**

"Tinnerman" wire-harness clamp with adhesive back is made from PVC extrusion. Retaining leg can be locked or unlocked for easy wire or hose insertion and removal. Various sizes are available. Eaton Corp., 25 Charles Ave., Massillon, OH 44646. 255

Taut-band movement panel meter featuresa 250° scale. Accuracy of the Model 1105is $\pm 2\%$. Price for 1-mA meter in 1000quantity is \$4.55 each. Faria Meter Corp.,Uncasville, CT 06382.**256**

Sealed pushbutton switches are "O"-ring sealed, bushing-to-panel and plunger-to-bushing, eliminating the need for external boots or other sealing means. Prices range from \$1.50 to \$2.52 in 100-piece quantities. Grayhill, Inc., 555 Hillgrove Ave., La Grange, IL 60525. **257**

Moving-coil motor features "ironless" armature for extremely high acceleration capability. Acceleration of up to 850,000 rad/sec² is achieved in the low-cost M-1030. Electro-Craft Corp., 1600 Second St. S., Hopkins, MN 55343. **258**

Brushless dc tachometer-generator incorporates an entirely new commutation principle to produce an output of 2V/1000 rpm with maximum ac ripple of 2% pk-pk, unfiltered. Life expectancy of Model TG-140 is over 50,000 hours. Linearity curve essentially goes through the zero point. Dynetics Corp., 8740 49th Ave. N., Minneapolis, MN 55428. **259**



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Circuits



Thick-film hybrid IF amplifier, Model AL-1014, has an operating center frequency of 440 MHz and a maximum noise figure of 2.5 dB. Maximum input VSWR is 1.5:1 and maximum output VSWR is 1.7:1. Minimum gain is 25 dB across the entire 120 MHz bandwidth with gain stability across the band of ± 0.5 dB. Input and output impedance is 50 Ω . Optimax, Inc., Colmar, PA 18915. **277**



Double-balanced mixer, Model 761, has a broadband characteristic that permits HF, VHF and UHF operation. Dimensions of the 8-pin hermetically sealed package are 0.785 by 0.39 by 0.235 inch. Maximum isolation specifications range from 40 to 45 dB (3 to 100 MHz) and 25 to 30 dB (100 to 1000 MHz). Price for 1 to 4 units is \$50 each. Summit Engineering Corp., 1820 S. 7th Ave., Bozeman, MT 59715. **280**



Encapsulated power supply PM 572 provides 5V dc at 1A and can be mounted directly on a PC board. Input requirement is $115 \pm 10V$ ac, 47 to 400 Hz. Other features for the 3.5 by 2.5 by 1.25 inch module include $\pm 0.4\%$ load regulation, $\pm 0.2\%$ line regulation, TC of 0.03%/°C and 1 mV rms ripple and noise. Unit price is \$58.95. Computer Products, 1400 N.W. 70th St., Box 23849, Fort Lauderdale, FL 33307. 283



YIG-tuned multipliers WJ-799 provide selected harmonic power over the 2 to 12.4 GHz frequency range. These units exhibit up to 3 mW of power delivered at 12.4-GHz output frequency with power available from 1 to 18 GHz. Inputs may range from 100 MHz to 2 GHz and be fixed-tuned or broadband. Up to 60 dB rejection of unwanted adjacent harmonics is available as an option. Watkins-Johnson Co., 3333 Hillview Ave., Stanford Industrial Park, Palo Alto, CA 94304. **278**



Solid-state time delay relay, Series MOR, comes with either factory-fixed or six adjustable delays that range from 0.5 sec to 5 min. Other features include 5A output contacts, built-in transient protection, temperature and voltage stability from -10° to 65°C and DPDT output configuration. Eight 0.25-inch quick-connect terminals provide the required interface. Prices range from \$8.70 to \$5.50. Omnetics, Inc., Box 113, Syracuse, NY 13211.



Programmable instrumentation amplifiers, Models 3602K, 3603K and 3604K, are encapsulated 2- by 2- by 0.4-inch units for PC board mounting. Models 3602 and 3603 each have four gain steps of 1, 10, 100 and 1000 and 1, 16, 256, 1024, respectively. For logic inputs, the unit is programmed in gain steps of 1 through 16, thus providing binary or BCD gain programming. Price is \$115 each. Burr-Brown Research Corp., International Airport Industrial Park, Tucson, AZ 85706. **284**



Eight-bit D/A converter DAC 329 comes complete with internal reference, output amplifier, resistor ladder and switches. The unit may be ordered with either 8-bit binary or two decades BCD coding. Fullscale output current is 2 mA. A high-speed (400 nsec settling) current output version designated DAC 329-1 is also available. Price for 1 to 9 quantity is \$29 each. Hybrid Systems Corp., 95 Terrace Hall Ave., Burlington MA 01803. **279**



Differential op amp, Model 46, features a slewing rate of $1000V/\mu$ sec with settling time to 0.1% in 100 nsec. Common mode rejection is 2000:1 for $\pm 10V$ input. Other features include a 6 dB/octave frequency roll off and 40-MHz bandwidth. Two versions are available, depending on the voltage drift required. Prices are as low as \$62 each in lots of 100. Analog Devices, Inc., Route 1 Industrial Park, Box 280, Norwood, MA 02062. **282**



Encapsulated power supply produces 200V at 25 mA from 115V, 50 to 400 Hz or 220V, 50/60 Hz. Designed primarily as a power source for cold cathode displays, the 3.5by 2.5- by 1.25-inch unit can be mounted directly on a PC board or used with mating socket. Ripple and noise is 2V pk-pk and operating temperature range is -25 to 70°C. Single quantity price is \$18. Instrument Displays Inc., Granite St., Haverhill, MA 10830. **285**

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Widebandamplifier,Model725,has arange of 50 kHz to 500 MHz with a gainof 27 dB. Gain flatness is ± 3 dB. Dimensions are 7.75 by 4.75 by 2.25 inches. Priceis \$150 each.Measurement SpecialtiesLaboratory Inc.,Box 3654,Santa Monica,CA 90403.**291**

Noise generator cards, Series 3600B, cover the 10 Hz to 5 MHz range with an output level of 3V rms open circuit. A dynamic range of 3.5 to 1 pk-to-rms is provided. Price is from \$154 to \$521 each. Elgenco, Inc., 1550 Euclid St., Santa Monica, CA 90404. 293

Operational amplifier, Model VDA-100, exhibits the following characteristics: <60 nsec settling time, >100 MHz bandwidth, 1 V/nsec slew rate, ±10V at 100 mA output and <0.16 nA/°C drift. Valid Data Corp., Box 441, Calabasas, CA 91302.

Voltage isolator SVI completely separates a low voltage source from its load. Unit accepts 0 to 5V dc. Field accuracy is $\pm 0.2\%$ full scale from 0 to 55°C and from 105 to 125 line volts. Halmar Electronics, Inc., 1544 W. Mound St., Columbus, OH 43223. 295

Three-in-one infrared detector features a windowless pyroelectric crystal with a wide operating temperature range – no repoling is required for average power inputs as high as 0.4W. A three-position switch permits selection of response times as short as 5 nsec or responsivities as high as 20 V/W into a 50Ω load. Molectron Corp., 930 Thompson Pl., Sunnyvale, CA 94086. **296**

Varactor-tuned transistor oscillator WJ-2800 provides 20 mW minimum microwave power in the 4 to 8 GHz frequency range. Two transistors in a push-pull configuration generate output power at the second harmonic of the fundamental oscillator frequency. Watkins-Johnson Co., 3333 Hillview Ave., Stanford Industrial Park, Palo Alto, CA 94304. **292**

Clock oscillator CO-231L drives 10 TTL loads within the 200 kHz to 30 MHz range. Only 0.3 inch high, the stability is better than $\pm 0.0025\%$ over 0 to 70°C. Price range is from \$20 to \$90. Vectron Laboratories, Inc., 121 Water St., Norwalk, CT 06854. 328

Three-phase bridge rectifiers, B-20 Series, are rated at 35A average dc current at 55° C and have a single-cycle surge rating of 400A at continuous load. Package dimensions are 0.75 by 2.25 inches. Tung-Sol Div., Wagner Electric Corp., 630 W. Mt. Pleasant Ave., Livingston, N J 07039. 329

Modular power supplies, T27 Series, provide the three most popular voltages: 5, ± 15 and 24V dc. Also three classes of regulation are available -0.01% (T27), $\pm 1\%$ (T27X) and 10% (T27Z). Modular PowerInc., 15302 Oak Canyon Rd., Poway, CA92064.**330**

High-voltage, high-current driver supplies 10A at 60V (pulsed). The dual circuit is housed in a 12-pin, TO-8 hermetic package. Unit price is \$10.32. Micropac Industries, Inc., 905 E. Walnut St., Garland, TX 75040. **331**

High-voltage bridge rectifiers are chassis mounted and fully insulated. Dimensions are 0.75 by 0.75 by 0.25 inch and the peak inverse voltage is 1 to 6 kV, rated at 50 mA. True rms voltage is 700 to 4200V. Computer Diode Corp., Pollitt Dr. S., Fair Lawn, N J 07410. **332**

Voltage sensor, Model 551 "Voltsensor Controller", detects low and high points of an analog signal generated by a transducer. Set points can be set independently for a trip point range of ± 25 V, or with separate trip point voltage reference up to ± 150 V. For 100 pieces, price is as low as \$47.60 each. California Electronic Mfg. Co., Inc., Box 555, Alamo, CA 94507. **333**

Circuits



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SOLID STATE (HYBRID) TIME DELAY RELAY CLASS 214CP-Magnecraft takes great pride in announcing this new time delay relay. Proven hinge-pin reliability designed into the output relay driven by a solid state circuit used in thousands of our timers, gives you the best low cost small size timing relay on the market. Operate delay timing ranges are offered between 3 hundred milliseconds and 4 minutes with $\pm 5\%$ repeatability and input supply of 115VAC.

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CIRCLE NO. 23

DUAL-INLINE-PACKAGED REED RELAYS CLASS 107DIP, 108DIP, 117DIP AND 118-DIP—Magnecraft is proud to announce its new DIP (dual-inline-package) line of 8-pin reed relays. These new relays are designed not only to be compatible with the standard packaging developed for integrated circuits, but to offer Magnecraft quality at a lost cost. This unique design gives further savings by offering the user the optimum in automated insertion and other economical installation techniques associated with printed circuit applications.

These fantastic new epoxy molded reed relays are ideal for use in circuits where high density packaging is essential. The 5VDC IC compatible versions of these relays will operate directly from TTL or DTL circuits.

Other standard coil voltages are available from stock in 6, 12, and 24 VDC as well as contact configurations in 1 form A, 2 form A, 1 form B, and 1 form C. Most versions are also offered with a choice of an internal clamping diode. The size of this device is a tiny .750 x .300 x .210 inches. CIRCLE NO. 24

SOLID STATE (HYBRID) PRINTED CIRCUIT TIME DELAY RELAYS CLASS 502PCSR AND CLASS 503PCSR—These new time delay relays make use of hybrid circuitry combining a monolithic silicon structure in the control function with a dry reed relay performing isolated circuit switching. Two fully adjustable timing ranges are afforded by using a remote pot or fixed resistor giving 0.2 to 100 seconds or 1 to 300 seconds each with \pm 2% repeatability. Standard coil voltages are available from stock in 12 and 24VDC as well as contact configurations in 1 form A rated at 1 amp and 1 form C at 0.5 amp. The size of this time delay relay is a mere 2.25" x 1.25" x .75".

CIRCLE NO. 25

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Circuits

Secondary lightning arrester, Model 1250-02, is a one-pole, two-wire device, rated 0 to 175V rms, that has a hermetically sealed spark gap plus silicon-carbide series element. Joslyn Electronic Systems, Div. of Joslyn Mfg. & Supply Co., Box 817, Santa Barbara Research Park, Goleta, CA 93017. **269**

Repeat cycle timers for periods as long as 1 month are available in special low power versions for battery operated systems. Power is only 100 μ W. Prices for the "B" series modules are under \$30 in 1000 quantities. Gould Ionics Inc., Box 1377, Canoga Park, CA 91304. **270**

Frequency multiplier accepts an input signal at 0 dBm in the 74.8- to 78.4-MHz band and provides 30 mW of CW power in the 2095- to 2195-MHz band. No tuning is required, and spurious signals are held at least 60 dB below the output signal level. Model 5001-00 is contained in a 23-inch³ housing and requires 160 mA drive at $\pm 28V$. Zeta Laboratories, Inc., 616 National Ave., Mountain View, CA 94040. **286**

High power hybrid assemblies of the "PACE/pak" Series contain passivated assembled circuit elements. Current handling capacity is up to 50A and such elements as SCRs, diodes, FETs, and others are contained in the single packages. Semiconductor Div., International Rectifier Corp., 233 Kansas St., El Segundo, CA 90245. **287**

Automatic dialing telephone module handles either local or long-distance phone numbers and eliminates the need for special lines. Price of model 904 138 is <\$100 each in quantity. G-V Controls Div., 101 Okner Pkwy., Livingston, N J 07039. 288

Broadband microwave IC power amplifiers cover the frequency range of 1.4 to 2.4 GHz with 1-dB bandwidths of 200 to 300 MHz. All units of the PA1100 Series operate from 24V dc. Power outputs of 0.5 to 5W are available with power gains of 10 to 20 dB and efficiencies greater than 25%. Prices range from \$625 to \$975 each. TRW Semiconductor Div., 14520 Aviation Blvd., Lawndale, CA 90260. **289** Everything you need to do statistical analysis ... without a computer ...



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E. EU-81A function generator. Sine, square and triangle wave output. 0.1 Hz to 1 MHz. Linear dial. External voltage control. \$245. EK-308



Equipment



Voltage-tuned receiver covers from 1 to 900 kHz, provides AM, FM and CW detection modes and has selectable IF bandwidths of 1.6, 20 and 50 kHz. Frequency is displayed on a 5-digit LED readout to an accuracy of ± 10 Hz. Digital AFC permits locking of the WJ-340's local oscillator in 10-Hz increments over the entire tuning range. Watkins-Johnson Co., 6006 Executive Blvd., Rockville, MD 20852. **260**



Pulse generators offer repetition rates from 1 Hz to 100 MHz with amplitude adjustable from 0.3 to 3V. Rise/fall times are less than 1 nsec. Model PM 5775 provides a single positive or negative output, while Model PM 5776 provides two outputs. Pulse widths are adjustable from 5 nsec to 100 msec. Philips Electronic Instruments, 750 S. Fulton Ave., Mount Vernon, NY 10550. **263**



Transient voltmeter, the "Peaklok", senses and displays the highest positive or negative peak value of any ac or dc voltage within the range from 0.1 to 1000V full scale. It responds to peaks as short as 1 μ sec in duration and holds the reading until reset. Meter accuracy is 1.5% of full scale. Pioneer/Instrumentation, 4800 E. 131st St., Cleveland, OH 44105. **266**



DMM measures ac and dc voltage, ac and dc current and resistance, yet sells for \$385. Model 3301 provides five ranges each for both ac and dc voltage and current and seven for resistance. Features include automatic zeroing, 3-1/2 digit nonblinking display, autopolarity, and flashing out-of-range indication. Options include battery pack and BCD output. Hickok Electrical Instrument Co., 10514 Dupont Ave., Cleveland, OH 44108. **261**



Portable dual-channel oscilloscope has dc to 35 MHz frequency response, deflection factors to 10 mV/div, sweep speeds to 10 nsec/div and delayed sweep. Operating modes include storage, variable persistence and normal. On storage, the Model 1703A can retain a waveform for more than an hour. Tentative price is \$2700 (Model 1702A without delayed sweep-\$2350). Hewlett-Packard Co., 1601 California Ave., Palo Alto, CA 94304. **264**



Expandable test system for MOS uses the pulser-per-pin approach. Software includes a machine-oriented program that translates functional commands into operational commands for each system unit, and an operator-oriented program to translate the operator's test requirements into functional commands to the system. System price range is from \$115,000 to \$300,000. E-H Research Laboratories, Inc., Box 1289, Oakland, CA 94604. **267**



Infrared thermometer makes non-contact surface temperature measurements of components as small as 0.1 inch to an accuracy of $\pm 1\%$. Model HSA-8E measures over a range of 0 to 600°F. The target area is defined by a light beam. Heat Spy Div., William Wahl Corp., 12908 Panama St., Los Angeles, CA 90066. **262**



Digital test probe, priced at \$59.95, operates from the 5 or 6V dc supply of the system under test. Logic levels are detected and defined by colored indicators. The "Dy-Nos-Stick" is individually available from stock. Nu-Concept Computer Co., 306 W. Logan St., Norristown, PA 19401. **265**



Solid-state timer with digital readout is offered in 2- or 3-digit versions, with the price starting under \$200 for a 2-digit unit. The end of the count is indicated by either an output signal or triggering of an oN/OFF control. AP Electronics, Inc., Industrial Rd., Alpha, N J 08865. **268**



There are holes in the type bar.

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There is further interesting information on the new Facit 3851 in this publication.

Facit 3851 - the conventional typewriter with input/output

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Auto-Pro 3500 Digital Plotter

Costing about \$1000 less than most other plotters and designed for the scientific user, the AP-3500 is simple to use with either time-share or small computers. The

combination of a digital-to-analog converter Y axis and an incremental stepper-driven X axis removes paper size restrictions and affords complete capability for 90% of all plotting/recording applications. The AP-3500 displays computer-calculated digital data or analog information directly. As a time-share plotter, information is accepted serially in ASCII arrangement at either standard or highspeed rates; as a minicomputer peripheral, data is accepted in bit parallel form, permitting even higher plotting speeds.

Plotting is in continuous form – forward or reverse – on roll chart paper, with only one data word and control character required to uniquely position the pen. Usable with modern high-speed data terminals, the AP-3500 plotter has overall accuracy of better than $\pm 0.25\%$ and is an ideal analytical tool in most scientific applications, ranging from biochemistry to circuit design. Request Bulletin AP-2402 for complete details.

Auto-Pro Intercouplers

Designed as a complete data system, Beckman's AP-3111 Intercoupler takes an analog input, converts the information to digital form, then prints and punches the data on an ASR-33 teletypewriter. Companion unit to the AP-3111 is Beckman's Auto-Pro 3109 which accepts up to 16 BCD data bits



in place of the analog input. Paper tape outputs of both instruments are directly time-share compatible and include automatic line number update and special control characters. Other features are local or remote control; preselectable reading interval and number of readings per sample. Request Bulletins AP-2400 and AP-2401 for complete details.



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Temperature Coefficient: (TYP.) 0.05% of or 5 mv/oc whichever is greater. Polarity: May be used positive or negative. Output voltage and current: See model listings. Output adjustment range: See model listings. Short circuit protection: Automatic circuit protects the power supply if the output is shorted continuously. Automatic return upon removal of short circuit.

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Ambient temperature rated: To 55°C.

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15.0±5%	2.0	LP15.0-2.0	49.75	44.75
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All Amperite Delay Relays are recognized under component program of Underwriters' Laboratories, Inc. for all voltages up to and including 115V. PROBLEM? Send for Bulletin No. TR-81.



Programmable 500-MHz universal counter/timer has an 8-digit in-line "Nixie" display. Measurements are referenced to an internal 10-MHz crystal oscillator with aging rate less than 0.3 PPM for 30 days. Price is \$1595. Eldorado Electrodata Corp., 601 Chalomar Rd., Concord, CA 94520. **315**

Varactor capacitance ratio meter, Model 172A, provides rapid, simultaneous measurements of the capacitance ratio of varactors at pre-selected upper and lower bias voltages and of their capacitance at chosen bias level. Available in December, it will be priced at \$2700. Boonton Electronics Corp., Rte. 287 at Smith Rd., Parsippany, N J 07054. **316**

Programmable test fixture for use with Tektronix 576 curve tracer permits programming of up to 11 sequential tests without manual setting of the 576 controls. A variable rate control allows the operator to select the test sequence rate. Fixture price is \$1400. Tektronix, Inc., Box 500, Beaverton, OR 97005. **317** Variable rise- and fall-time pulse generator, Model 116, is a 50-MHz unit priced at \$850. Rise and fall times are linear and independently variable from less than 5 nsec to greater than 0.5 sec. Systron-Donner Corp., Datapulse Div., 10150 W. Jefferson Blvd., Culver City, CA 90230. 318

Repeat cycle timer covers from 0.02 to 300 seconds in seven timing ranges with repeat accuracy of $\pm 1\%$ of dial setting. Model TM101 is all solid-state, operates on 115V, 50/60 Hz (+10% or -15%), and is guaranteed for 500 million operations or 5 years. Price is \$42 each in lots of 100. Regent Controls, Inc., Harvard Ave., Stamford, CT 06902. **319**

DVM/Multimeter, Model 7004, uses bipolar integration. There are five ranges each of dc and ac volts, dc and ac current and resistance. Price is \$650 for the 4-1/2-digit multimeter, \$95 extra for 12V battery pack if desired. Systron-Donner Corp., 888 Galindo St., Concord, CA 94520. **320**



Why our ½ -ounce, 100,000,000-cycle, \$4.00 EF keyboard isn't perfect for every application

Very simply, it's a flat board. It measures just 0.156 inch above the panel and 0.430 inch below the panel, including the depth of the pins. There are no moving parts. There's no key travel. This board is ideal for control panels or other places where you need not duplicate the feel of a typewriter. (Other models do offer key travel.)

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CIRCLE NO. 64

AC level converter for monitoring and recording ac voltage or current levels, Model 11-5201-18, has 15 msec response to a step input, which allows accurate recording of transients less than one cycle in duration on 50- or 60-Hz power lines. Measurement range is from 50 mV to 700V rms or 0.5 to 10A full-scale. Frequency response is flat from 50 to 5000 Hz. Gould Inc., Brush Div., 3631 Perkins Ave., Cleveland, 321 OH 44114.

High power pulse generator delivers over 31 kW of peak power at 1.5% duty factor. The output of the Model 360 is continuously variable to 2500V. Price each is \$4990. Velonex, A Varian Div., 560 Robert Ave., Santa Clara, CA 95050. 322

Solid state wattmeter, Model M1/SC1, measures true rms voltage, current and electrical power over the frequency range of 5 to 100 kHz. Power range is 20W to 20 kW full scale. Price complete with recorder output is \$495. Wave Energy Systems Inc., Newtown Commons, Newtown, PA 18940. 323

Equipment

Series LV thermal control units accommodate up to 2 kW of dissipation by semiconductors mounted on heat sinks clamped to a temperature-controlled pipe. They accommodate up to 40 TO-3 transistors, and will maintain heat sink temperatures within ±2°C over the range from 60 to 200°C. Units are sold either as complete systems or modules. Wakefield Engrg., Inc., Systems Div., Audubon Rd., Wakefield, MA 01880. 324

Sonic tester, for detecting voids in any material, Model 301, operates at 13.4 kHz with power demand of 4W from either 115V ac or battery. Model 301 weighs only 6 lb and measures 9 by 6 by 6 inches. Tek Tran, Box 460, Newark, OH 43055. 325

Modular photomicrographic attachment camera system, Model PM-10, features both automatic and manual camera bodies that use interchangeable film backs. holders and other accessories. The Model PM-10 system adapts to existing microscopes of all makes. Olympus Corp. of America, 2 Nevada Dr., New Hyde Park. NY 11040. 326



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CIRCLE NO. 53

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CIRCLE NO. 54



Digital repeater for synchro-to-digital conversion is described in six-page Bulletin 67-11B. Theory of operation, applications and full specifications are included. Theta Instrument Corp., 22 Speilman Rd., Fairfield, N J 07006. 297



Optoelectronic components including displays, LEDs, IR emitting diodes and phototransistor opto-isolators are described in this 12-page catalog. European Electronic Products Corp., 10150 W. Jefferson Blvd., Culver City, CA 90230. 301





Electromagnetic delay lines are featured in Catalog No. 10, a 20-page booklet giving specifications and descriptions for a broad range of delay lines. ESC Electronics Corp., 534 Bergen Blvd., Palisades Park, N J 07650. 304



Selector switches are described in a 16page catalog with complete electrical and mechanical specifications for the CTS 223 Series. Detailed printed circuit switch mounts for both perpendicular and parallel terminal mount styles are included. CTS Corp., 1142 W. Beardsley Ave., Elkhart, IN 46514. 298



Capacitors, filters and microcircuits are featured in this 228-page product specifier. Capabilities in thin and thick films, hybrid microcircuits, chip arrays and DIPs are discussed along with technical data on capacitors and filters. Copies are available by letterhead request to AVX/Aerovox, New Bedford, MA 12741.



Electronic keyboard system utilizing a scanning technique is described with a diagram, specifications and a listing of standard and optional features. Also included is a six-page keyboard designer's specification sheet to aid in keyboard design. Cherry Electrical Products Corp., 3600 Sunset Ave., Waukegan, IL 60085. 305



Thermocouple meters and pyrometers are the subjects of this four-page brochure that details the Series 7000 meters and a new low-cost electronic readout meter. Dimensions, various options and prices are included. Omega Engineering Inc., Box 4047, Stamford, CT 06907. 299



Microelectronic packages are covered in this 16-page illustrated catalog with dimensional drawings of 45 standard configurations and construction details of over 100 standard packages. Sealox Div., National Beryllia Corp., Greenwood Ave., Haskell, N J 07420. 302



Core memory systems are introduced in a

catalog describing the 400 Series with storage capacity from $4k \times 9$ bits to 65k× 36 bits. Fabri-Tek, Inc., 5901 S. County Rd. 18, Minneapolis, MN 55436. 306



"A Unique Concept in Printed Circuit Relays" is the title of an eight-page catalog describing printed circuit relay that plugs directly into a PC board without sockets or soldering. Information concerning PC board preparation and prototype testing is included. Printact Relay Div., Executone, Inc., 29-10 Thomson Ave., Long Island City, NY 11101. 300



Electrical/electronic measurement system is described in an eight-page catalog. Basic components are arranged to provide Wheatstone, Kelvin, inductance or capacitance bridges; differential voltmeters; millivolt potentiometers; ac/dc transfer unit; and others. Laboratory Systems Research, Inc., 2732 29th St., Boulder, CO 80303. 303



Designer's handbook of reed and mercurywetted contact relays is available in the fifth edition. It contains a glossary of terms, principles of operation, applications, design requirements, specifying and testing data and new product information. Copies are available by letterhead request to Magnecraft Electric Co., 5575 N. Lynch Ave., Chicago, IL 60630.

Literature

"Optogram" is a monthly technical bulletin describing customer applications, new products and exciting activities in the optical and laser field. A. D. Jones Optical Works, Inc., 64 Cambridge St., Burlington, MA 01803. **307**

Indicator lights, light-emitting diodes and incandescent lamps are completely described in an eight-page catalog. General Illumination, Inc., 2233 University Ave., St. Paul, MN 55114. **308**

Data sets and modems are the subject of a 12-page brochure describing the Series 1300 transmitter/receiver units that greatly improve the efficiency of dial-up data systems even where telephone line performance is seriously deteriorated. Several pages of the brochure are devoted to design features and circuitry that make this high-performance possible. Dataserv. 770 Airport Blvd., Burlingame, CA 94010. **309**

FET-input op amp with fractional picoamp bias current is described in a two-page data sheet with specifications, prices and application information. Analog Devices, Inc., Box 280, Norwood, MA 02062. **310**

Multiple-output power supplies are described in a catalog containing condensed data on modular units and custom units for computer CRT terminals, card reader and digital cassette OEM applications. Also included is information on MIL-spec custom units and a four-output lab supply. Astro-Space Labs., Inc., Research Park, Huntsville, AL 35806. 311

Thin-film resistor networks for D/A and A/D converters feature utmost temperature stability and tracking, and are covered in a data sheet describing three models and various packaging options. Analog Devices, Inc., Pastoriza Div., Box 280, Norwood, MA 02062. 312

Conductive coatings are covered in this six-page booklet from Acheson Colloids Co., Box 288, Port Huron, MI 48060. **313**

Single-ended CATV amplifiers are discussed in a position paper which reviews basic CATV amplifier designs. Pro and con aspects of push-pull, split-band, distributed and single-ended amplifiers are considered. AEL Communications Corp., Box 507, Lansdale, PA 19446. **314**



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CIRCLE NO. 57

Spectrum analyzers, sweep generators, programmable attenuators and lumpedcomponent miniature low-pass and bandpass filters are featured in a 20-page illustrated catalog with physical and electrical characteristics, applications and prices. Texscan Corp., 2446 N. Shadeland Ave., Indianapolis, IN 46219. 334

Panel-mounted accumulator that totalizes events occurring during a programmed interval at rates up to 1 MHz is described in Bulletin 2457. Electronic Instruments Div., Beckman Instruments, Inc., 3900 River Rd., Schiller Park, IL 60176. **335**

Precision components catalog contains 446 pages with over 35,000 electrical and mechanical components in this 35th edition. PIC Design Corp., Box 335, Benrus Center, Ridgefield, CT 06877. **336**

Solid-state pushbutton module featuring a magnetically actuated Hall effect integrated circuit chip is described in Product Sheet 101SN1. Micro Switch, Div. of Honeywell Inc., 11 W. Spring St., Freeport, IL 61032. 337

"A Reliable Plastic Power Transistor Family Aimed at the Heart of Television Applications" is the title of Publication 1CE-406 which describes the procedures that produce the mean-time-before-failure of 275,000 hours for RCA-2N6177 family transistors. RCA Commercial Engineering, Harrison, N J 07029. **338**

Solid tantalum capacitors of the ENS Series, with values ranging from 0.0047 to 330 μ F and ratings from 6 to 100V, are covered in Bulletin 830. National Components Industries, Inc., 5900 Voss Rd., West Palm Beach, FL 33407. **339**

Switch catalog has 28 pages providing a guide to the basic criteria for switch selection, and complete specifications and ordering information for a variety of switches. Tech Labs, Inc., Bergen and Edsall Blvds., Palisades Park, N J 07650. 340

Chip capacitor data sheet, CZ5B, features hundreds of "Vee Jem" values and includes suggested mounting methods, detailed specifications and close-up photos. Vitramon, Inc., Box 544, Bridgeport, CT 06601. 341

Literature

"Lock-In Amplifier Versatility" is the title of a 12-page specification and application guide which describes many different lock-in systems that can be created at minimum cost by the addition of special purpose plug-in modules. Ithaco, Inc., 735 W. Clinton St., Ithaca, NY 14850. **342**

Drafting aids catalog contains eight pages describing unique drafting and engineering aids, including zero center scale and "Decimal Keeper" slide rule. Devonics Inc., 1515 Chatsworth Blvd., San Diego, CA 92107. 343

Digital audio signal delay unit, Model 101, is described with illustrations and applications in a six-page brochure. Gotham Audio Corp., 2 West 46th St., New York, NY 10036. 344

Solid-state time code generator module is the subject of Bulletin CG526 which includes specifications, dimensional data and information on a 7-segment LED time display. A. W. Haydon Co., 232 N. Elm St., Waterbury, CT 06720. 345

System 390 universal card tester for automatically testing digital, analog and hybrid PC boards, modules and components is described in a 16-page brochure. The system is discussed in general terms and specific details. Instrumentation Engineering, Inc., 769 Susquehanna Ave., Franklin Lakes, N J 07417. **346**

Test report on the MD53 and RMD53 highdensity, multi-pin series connectors has eight pages showing tests performed, MIL spec requirements and results. Connector Div., Microdot Inc., 220 Pasadena Ave., South Pasadena, CA 91030. **347**

Digital head selector for Datum-Series 1/2inch IBM-compatible recording heads is designed in the form of a circular slide rule and provides essential technical data on the company's line of tape heads. Nortronics Company, Inc., 8101 Tenth Ave. N., Minneapolis, MN 55427. **348**

Digital panel meters, a limit set comparator and a digital multimeter are described, along with pertinent specifications and prices, in a four-page short-form catalog. Digilin, Inc., 1007 Air Way, Glendale, CA 91201. **349**


CIRCLE NO. 50



51 sketches showing photo controls for

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CIRCLE NO. 49



83

Additional "-Right and Wrong Ways to Design MOS Systems"

After complimenting Evelyn Berezin on her article on MOS systems (July 1 EDN/ EEE), Rob Walker, manager of Micromosaic Engineering, Fairchild Semiconductor, contributed these additional points on MOS design:

- "1. Digital simulation is of great aid in verifying a design; for example, worst case combinations of gate delays are hard to analyze on a breadboard. Some types of dynamic logic are essentially impossible to breadboard, and simulation is the only answer. Digital simulation is also helpful for test pattern generation.
- 2. An advantage of breadboarding the MOS design (after partitioning) relates to system checkout. Chances are all arrays won't be completed simultaneously, and will dribble in to the customer one at a time. By proper impedance and voltage matching, the LSI array may replace breadboard components one at a time, shortening checkout time.
- 3. Part of the extra engineering cost of

LSI goes into a very complete analysis of the design. Timing, critical delays and worst case tolerances are studied in greater detail than normally afforded conventional designs. We are all aware of the high cost of field modifications required because of incomplete or careless analysis. To some extent then, the conversion cost of LSI is partly an investment in customer satisfaction."

Gentlemen:

Recently, while making a technical inquiry about silicon rubber wire (to General Electric), a secretary referred me to their semiconductor department with this quip: "They make silicone transistors there."

Thought this might be good for the Signals & Noise Dept.

Dale E. Barbour Systems Engineer Magnavox Research Labs Torrance, CA 90503



make thermal runaway a thing of the past!"

Earth

"A planet doesn't explode of itself," said drily the Martian astronomer gazing off into the air. "That they were able to do it is proof that highly intelligent beings must have been living there." —John Hall Wheelock



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CIRCLE NO. 60



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Motor and gearmotor overspecification is the subject discussed in the "Chief Engineers Handbook" section of *Motorgram* (Vol. 51, No. 3). Relationships between custom specifications, performance and cost are discussed. Bodine Electric Co., 2500 W. Bradley Pl., Chicago, IL 60618. **350**

Tape recorderHandbook 1330 is a practical guide for users of instrumentationtape recorders.This 43-page handbookcontains an introduction to magnetic tapesystems, a glossary of instrumentationterms and a concise explanation of howmagnetic heads work.Bell & Howell Co.,360Sierra Madre Villa, Pasadena, CA91109.351

"Testing for Forward-Bias Second Breakdown in Power Transistors" is the title of Application Note AN-4573. This six-page note describes a non-destructive test circuit that determines the forward-bias second-breakdown safe operating locus for power transistors. Test circuit diagrams, typcial waveforms and figures illustrating the physical process of second breakdown are included. RCA Commercial Engineering, Harrison, N J 07029. **352** "What Every Temperature Chamber User Should Know About CO_2 " is a booklet intended to help users get better utilization of the product. Techniques are described that can save engineering time, improve safety, reduce chamber maintenance and cut down on CO_2 consumption. Vacon, 2946 Adams Ave., San Diego, CA 92116. 353

IC voltage regulators, Types 723 and 823, are described in a 17-page application note including information on parameters and a discussion of bias limitations, ripple rejection, external sensing, thermal effects, current limiting, current capability and special applications. Teledyne Semiconductor, 1300 Terra Bella Ave., Mountain View, CA 94040. **354**

"Primer of Plant Noise Measurement and Hearing Testing" is a 24-page booklet which gives a capsule analysis of current government regulations enacted to protect the hearing of nearly everyone exposed to industrial noise hazards and describes the techniques and equipment used to measure plant noise and monitor employee hearing as required by the new statute. General Radio, 300 Baker Ave., Concord, MA 01742. **355** "Thyristor Selection and Calculations for Pulse Applications" is the first title in a new series of "Tech Tips" articles on the selection, application and use of discrete power semiconductors and subsystems. Westinghouse Electric Corp., Semiconductor Div. Marketing Services, Youngwood, PA 15697. **356**

Low-noise FETs are compared with lownoise bipolar transistors in a five-page application note discussing noise relationships. Included are basic definitions, how to determine noise figures, test procedures and information on the use of equivalent noise and current sources. Teledyne Semiconductor, 1300 Terra Bella Ave., Mountain View, CA 94040. 357

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